

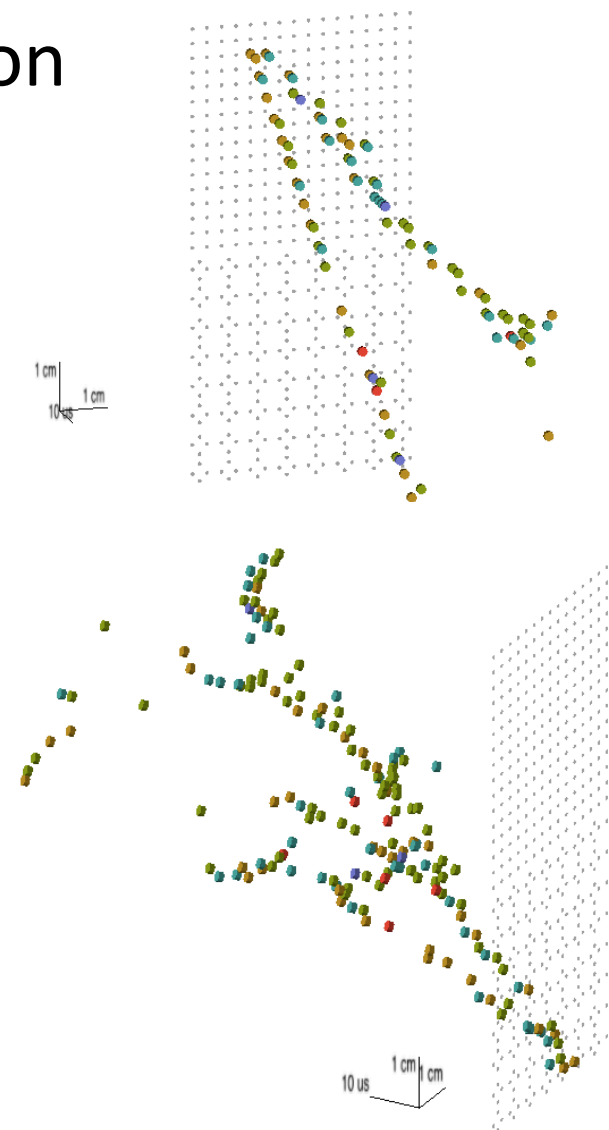
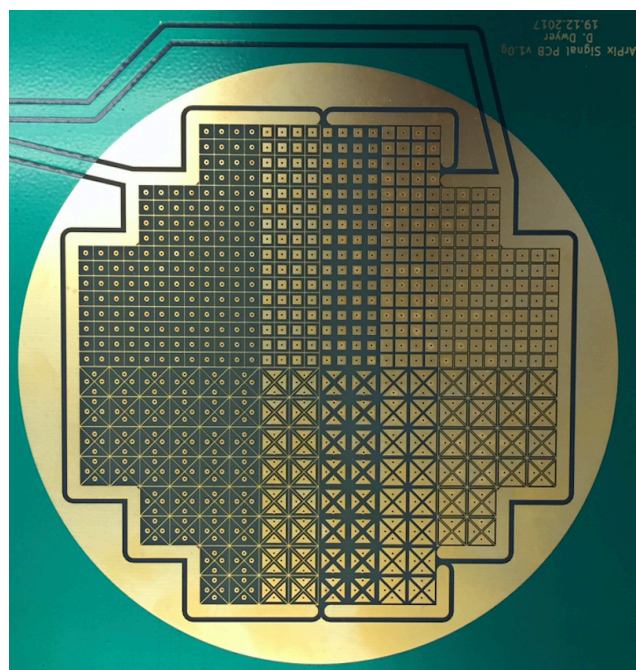
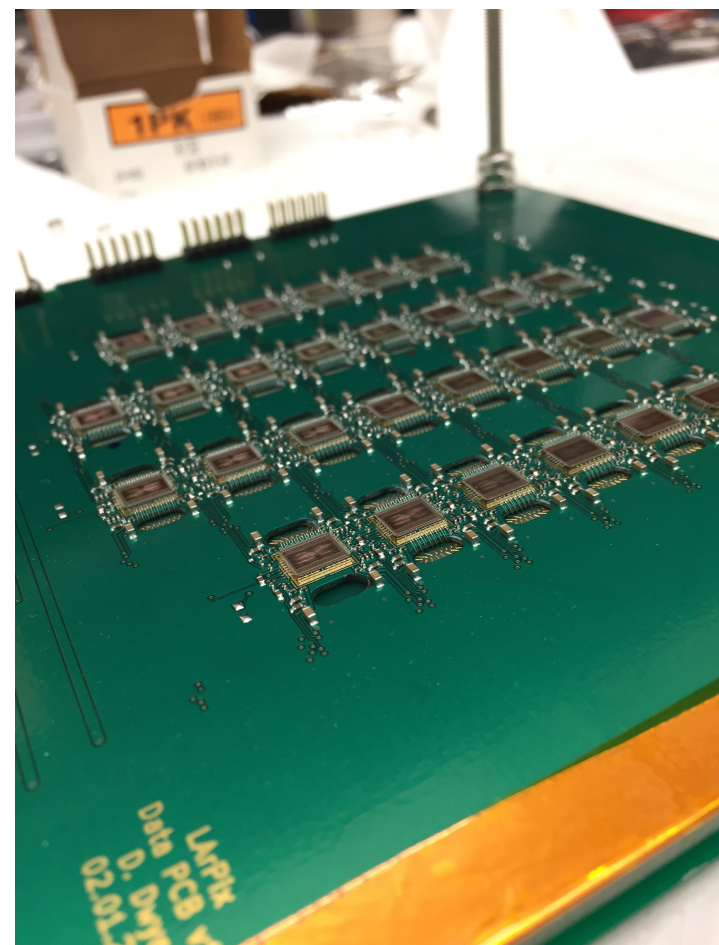
LArPix Readout: Status and Plans

Dan Dwyer (LBNL)

ArgonCube Collaboration

Meeting

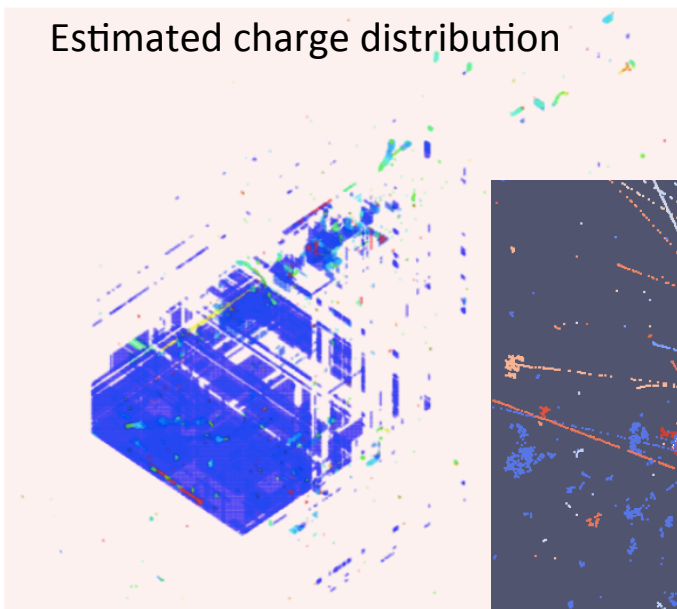
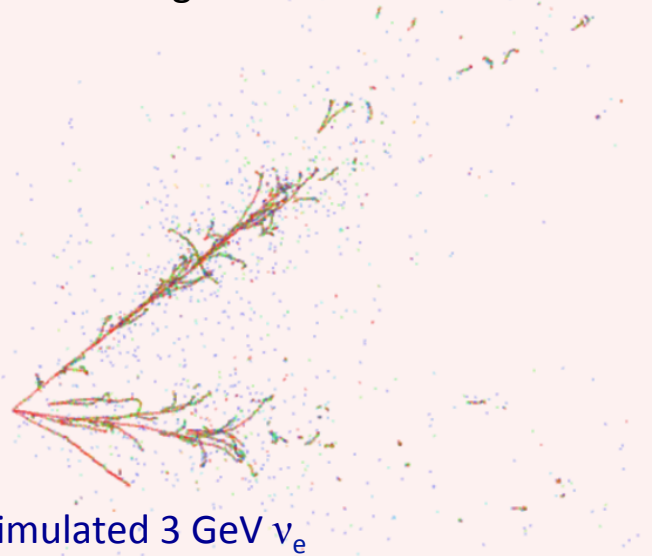
June 12, 2018



Ambiguities in projective wire readout:

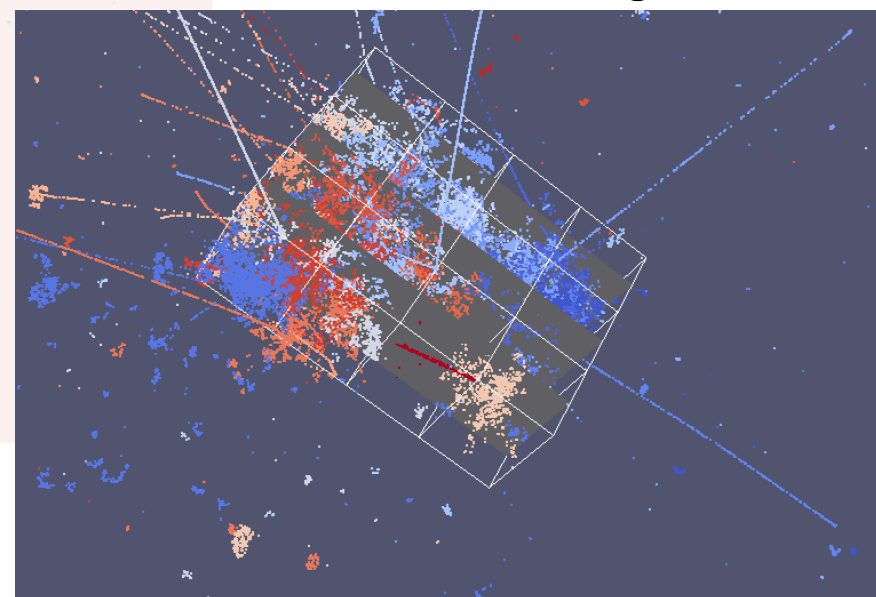
Actual charge distribution

Estimated charge distribution



DUNE Near LArTPC:

High neutrino rate exacerbates ambiguities.



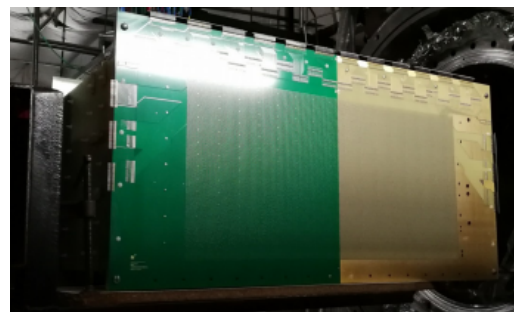
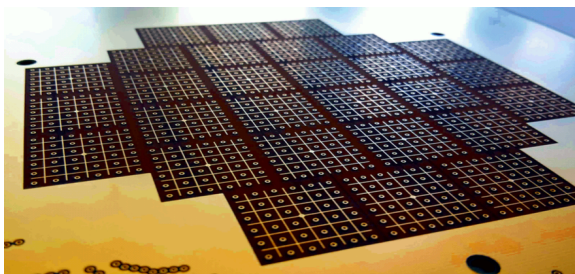
Example neutrino signals from one LBNF spill

Pixel Readout Development

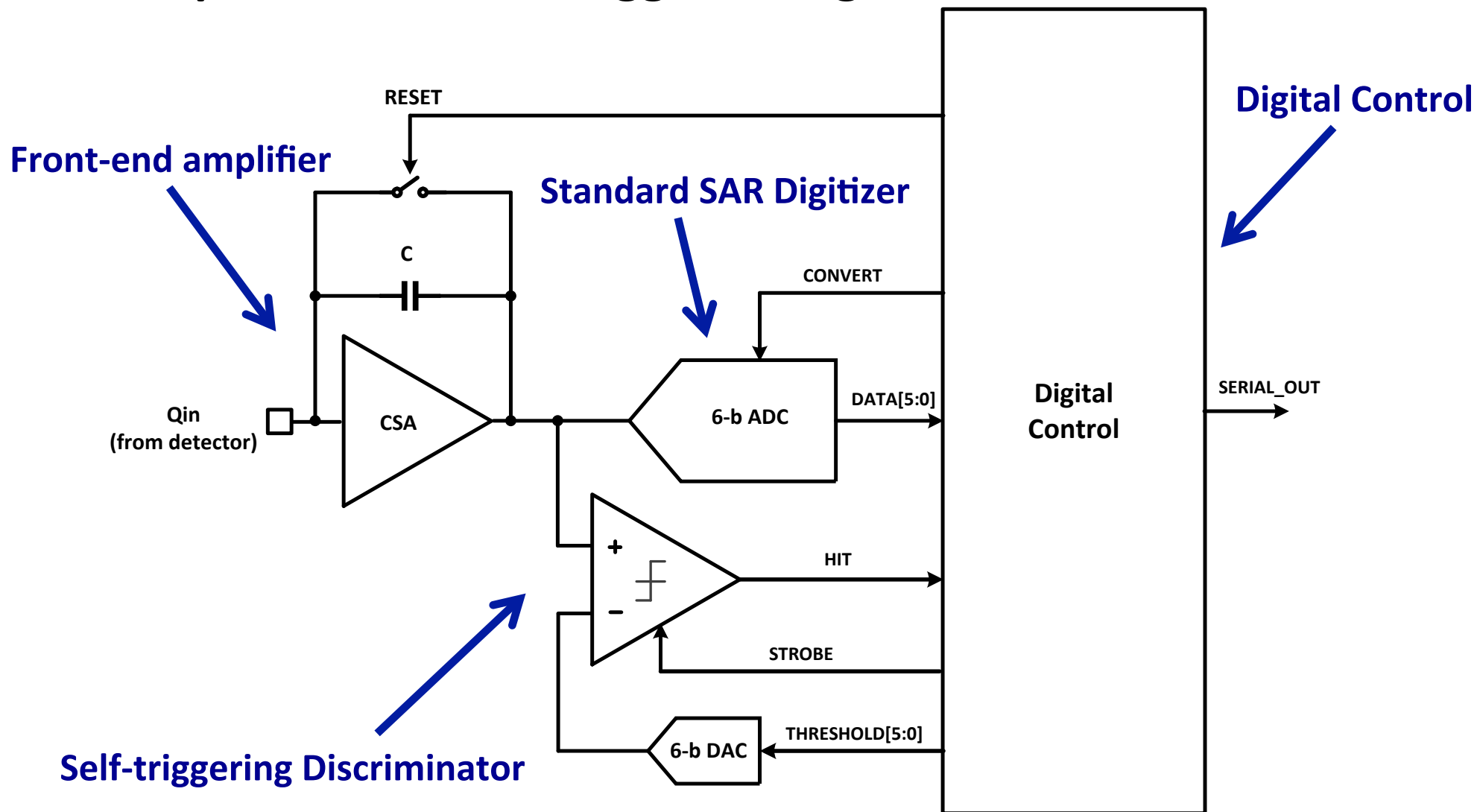
Demonstration of pixel sensor feasibility (Bern/ArgonCube)

Progress with in-beam tests (PixLAr)

→ Low-power pixel electronics (LBNL)



Amplifier with Self-triggered Digitization and Readout



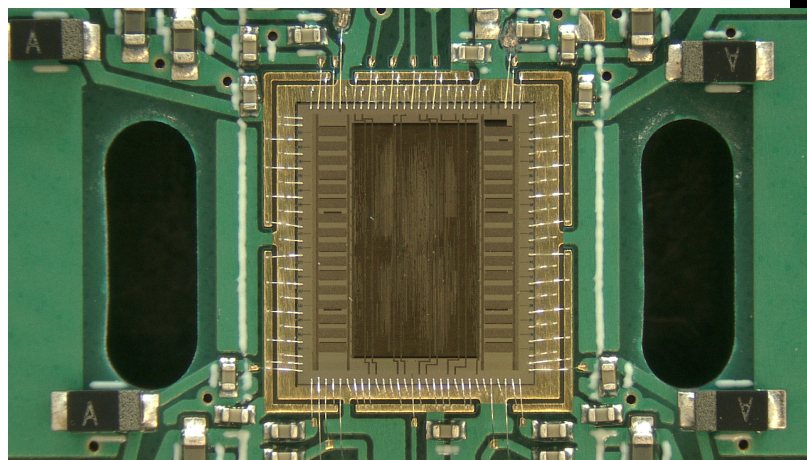
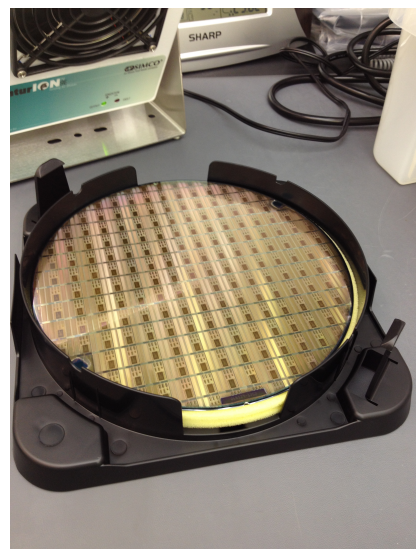
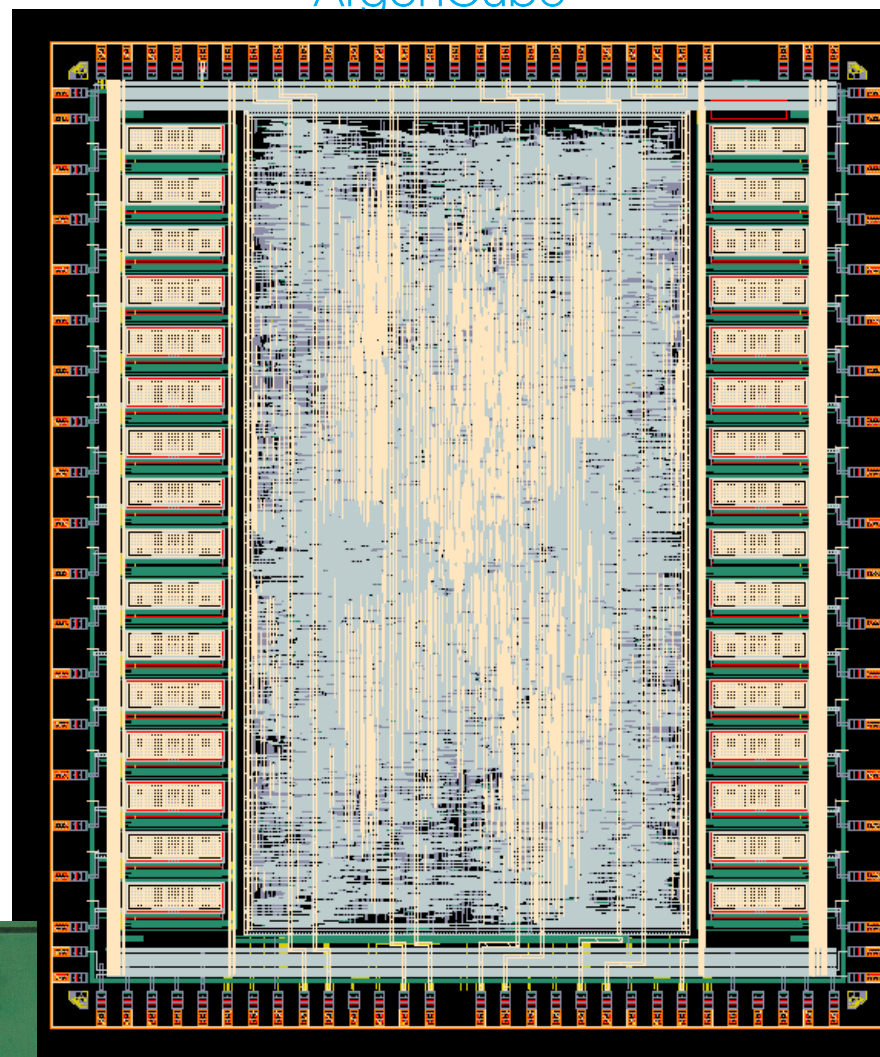
Achieve low power: avoid digitization and readout of mostly quiescent data.

LArPix-v1 ASIC:

- Dec. 2016: Design began
- June 2017: Submitted for fabrication
- Oct. 2017: First chips, test boards @ LBNL
- Dec. 2017: Bench tests successfully completed
- Jan. 2018: Assembled sensor, integrated LArTPC

Progress since last collaboration meeting:

- Feb. 2018: First tracks from true 3D LArTPC @ LBNL
- Mar. 2018: Developed integrated control system
- Apr. 2018: Assembled scalable 512-channel system, operated in 60-cm-drift TPC @ Bern
- May 2018: Operated 832-channel system @ LBNL

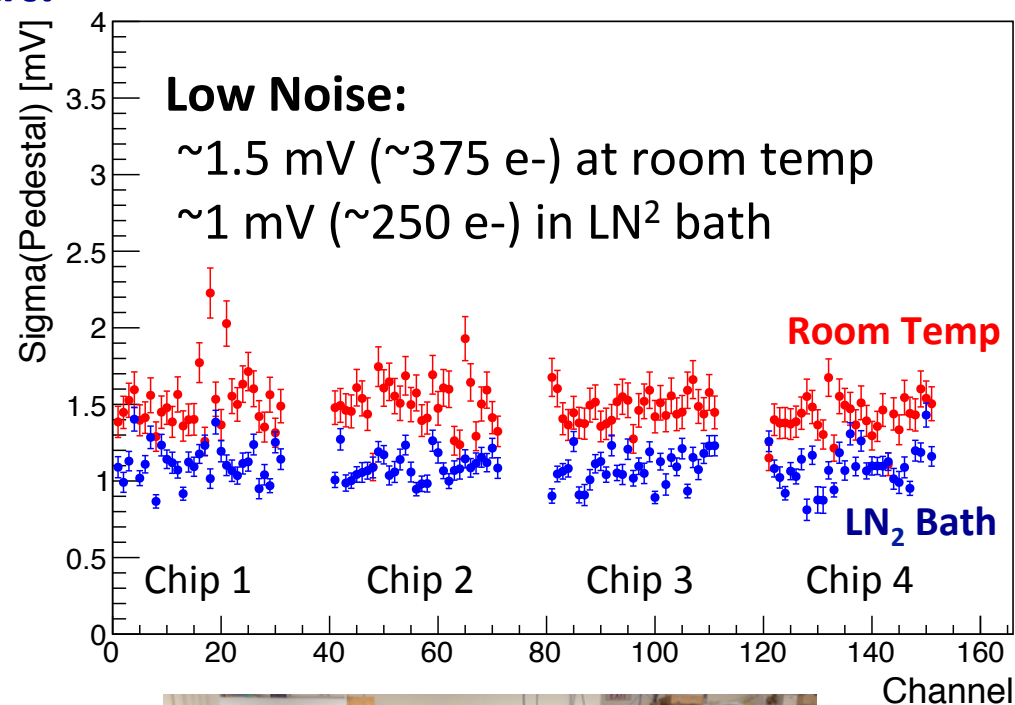
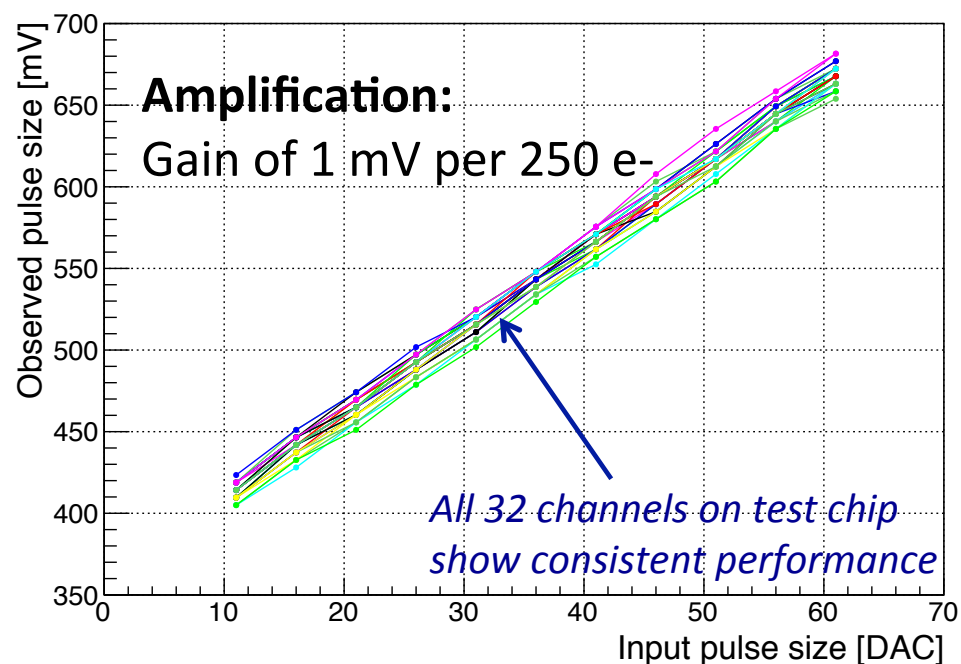


Process: 180nm bulk CMOS

Design and testing team @ LBNL:

D. Dwyer, C. Grace, M. Garcia-Sciveres, A. Krieger, D. Gnani, T. Stezelberger, S. Kohn, P. Madigan, H. Steiner

Demonstrated low-noise low-power cryogenic amplification, digitization, and readout:

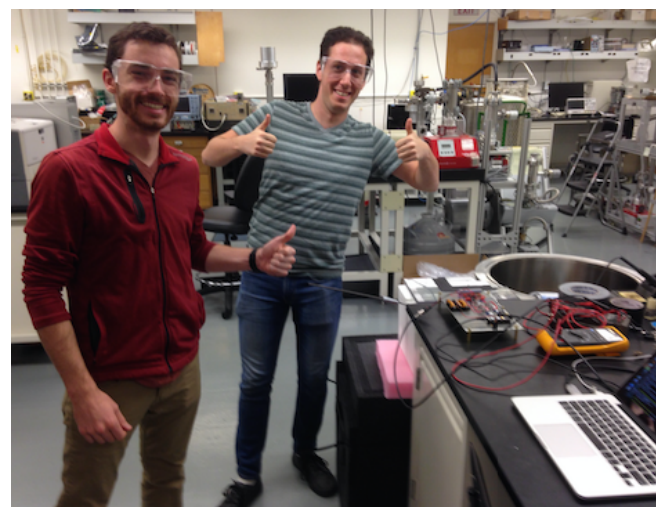


Low Power:

Average power for 128-channel readout:

- Analog: 24 μ W/channel
- Digital: 38 μ W/channel
- **Total: 62 μ W/channel**

See talk from DUNE Collaboration Meeting (January 2018) for more details.

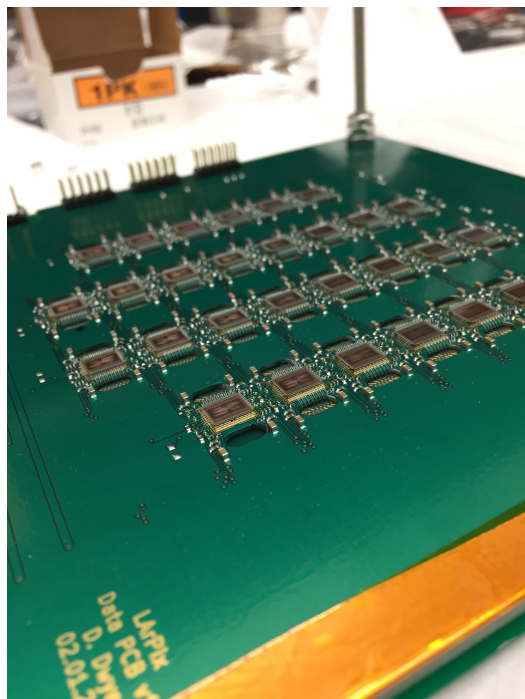


P. Madigan, S. Kohn: drove testing effort

Developed Prototype Control System:

- Warm electronics for LArPix sensor operation
- Provides power, reference voltages, clock, data I/O, and integrated DAQ system
- Main components:
 - Off-the-shelf Cmod FPGA module (\$60): Provides real-time clock, I/O
 - Raspberry Pi Zero (\$5): Complete DAQ system, control computer
- Requires: 5V power supply or battery, ~400 mA average current.
- Access via wifi

Pixel system



Inside Cryostat

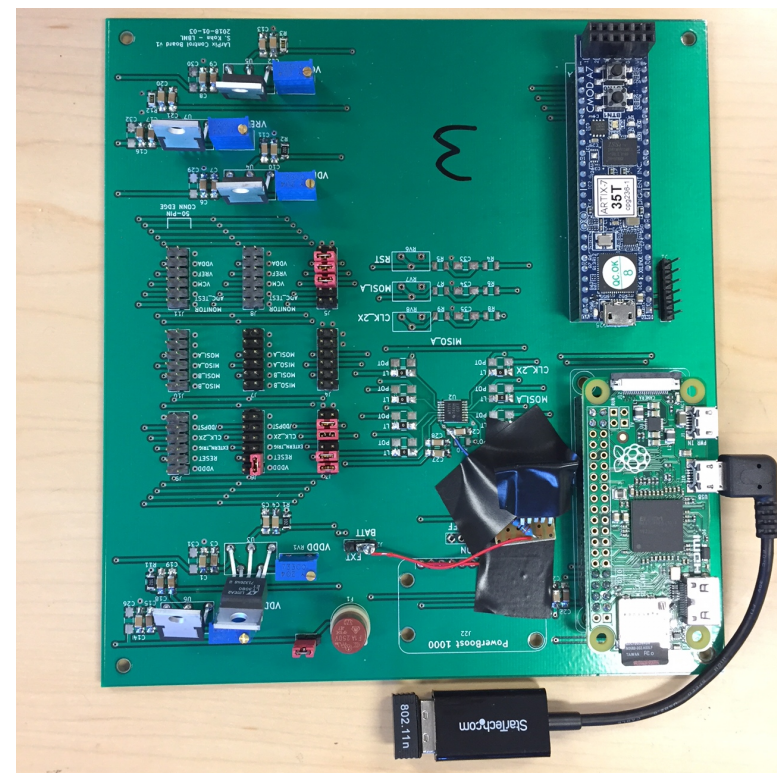
50-pin ribbon cable



Existing layout should scale to ~8000 pixels.

With minor changes to FPGA firmware and PCBs, should support up to $\sim 10^5$ pixels.

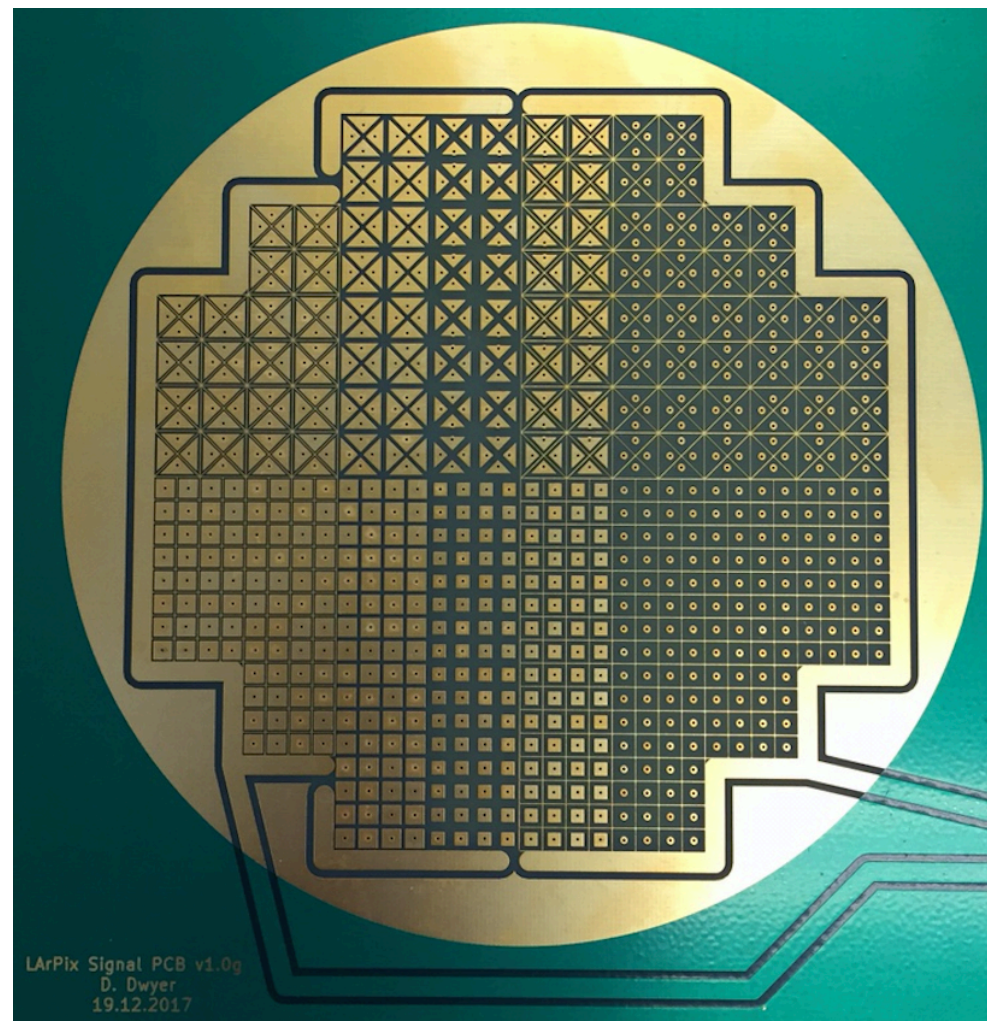
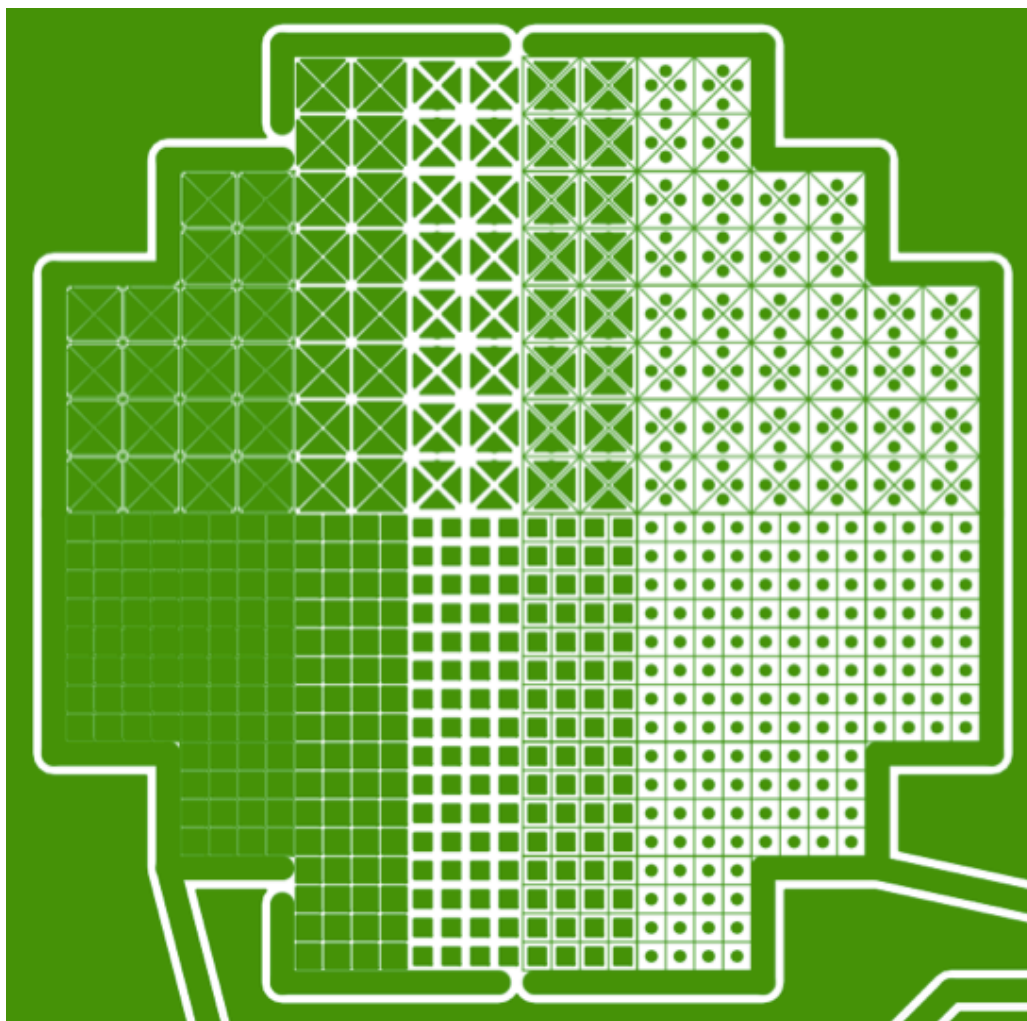
Control System



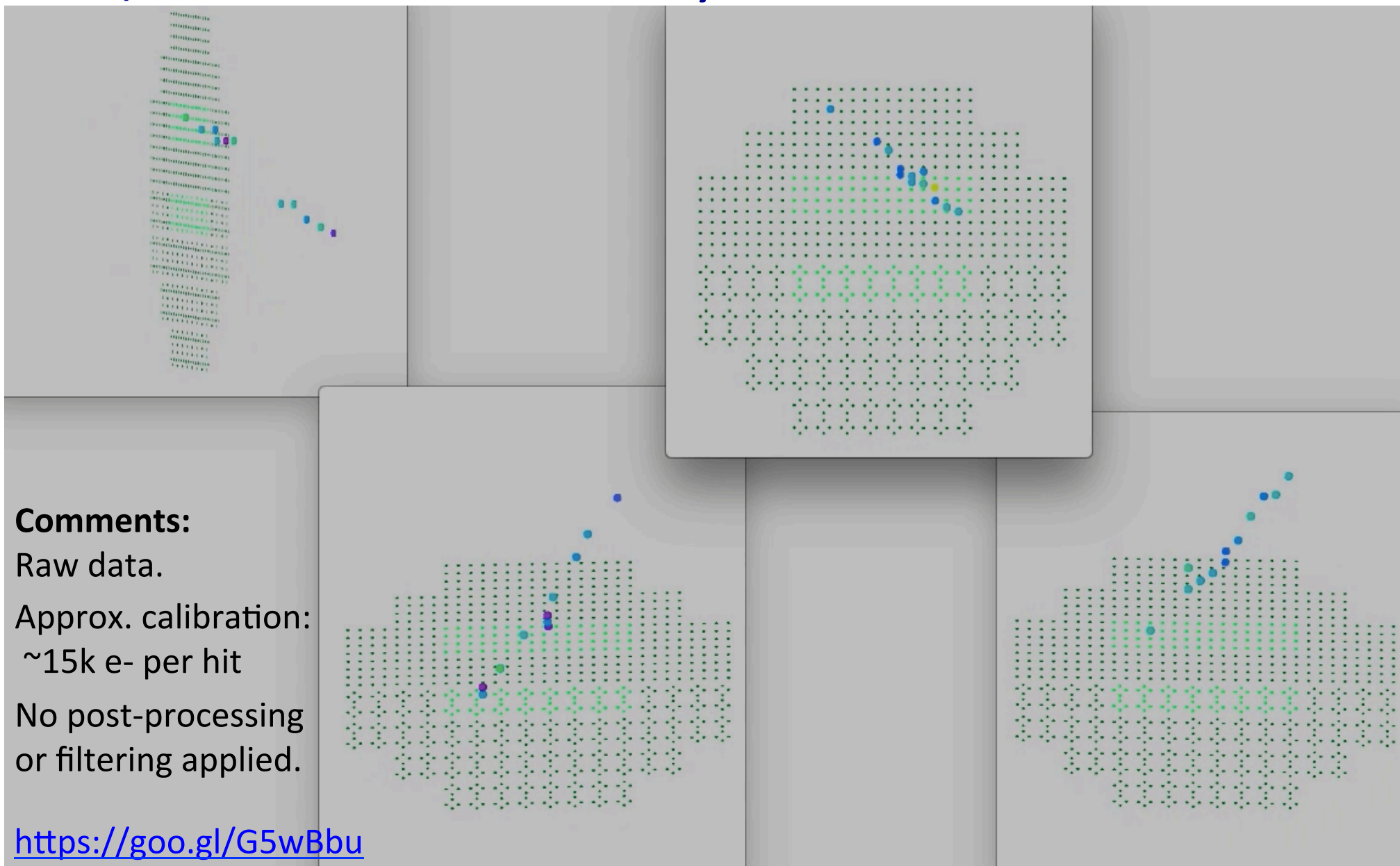
Outside Cryostat

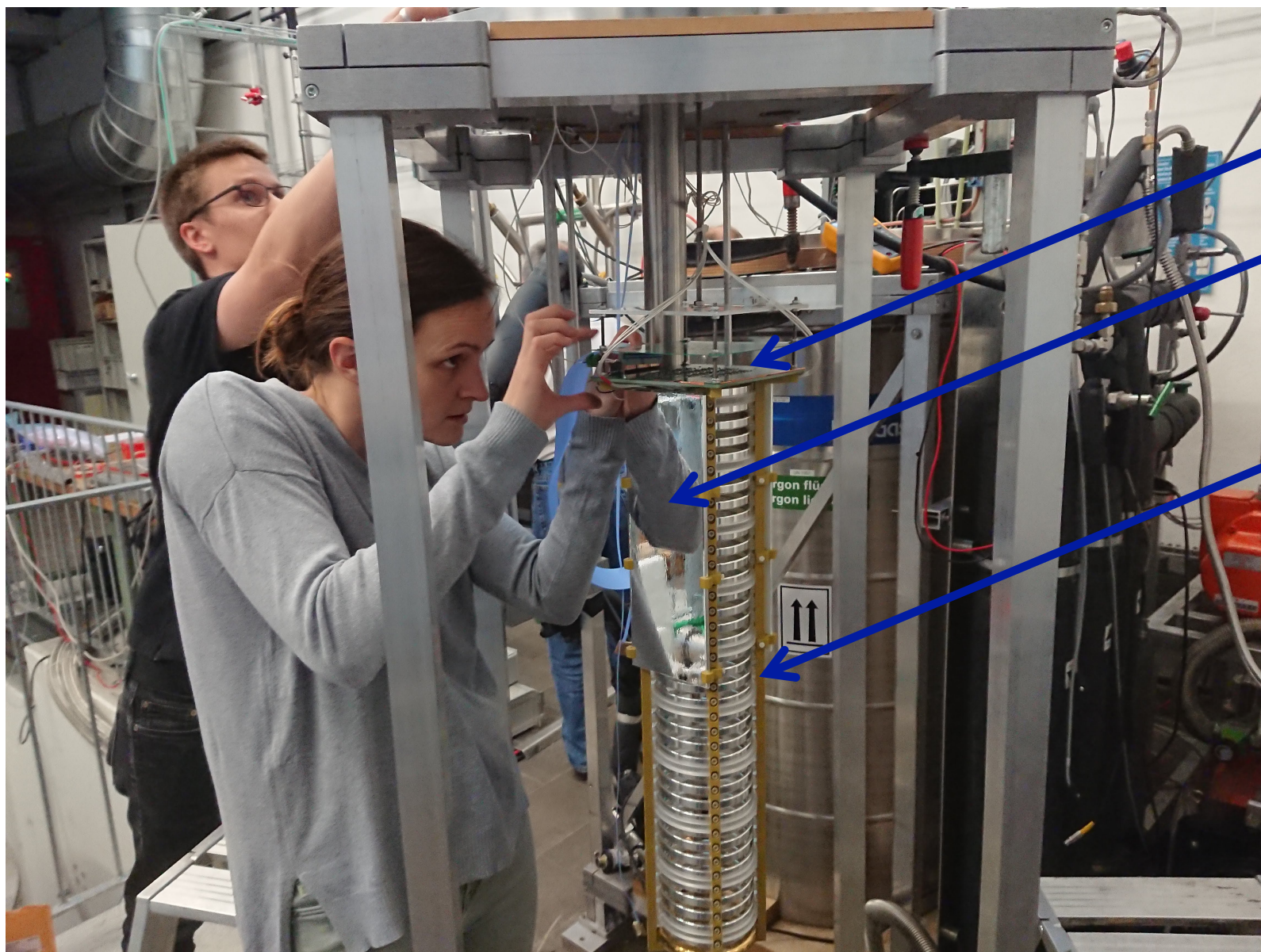
Prototyped a variety of pixel geometries

Sensor PCB board designed to fit Bern Pixel Demonstrator TPC
Includes 10 different pixel geometries/configurations



Feb. 13, 2018: Detected first cosmic ray tracks





LArPix Readout

ArCLight System

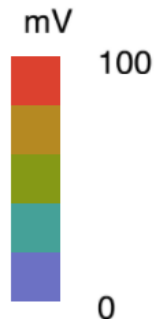
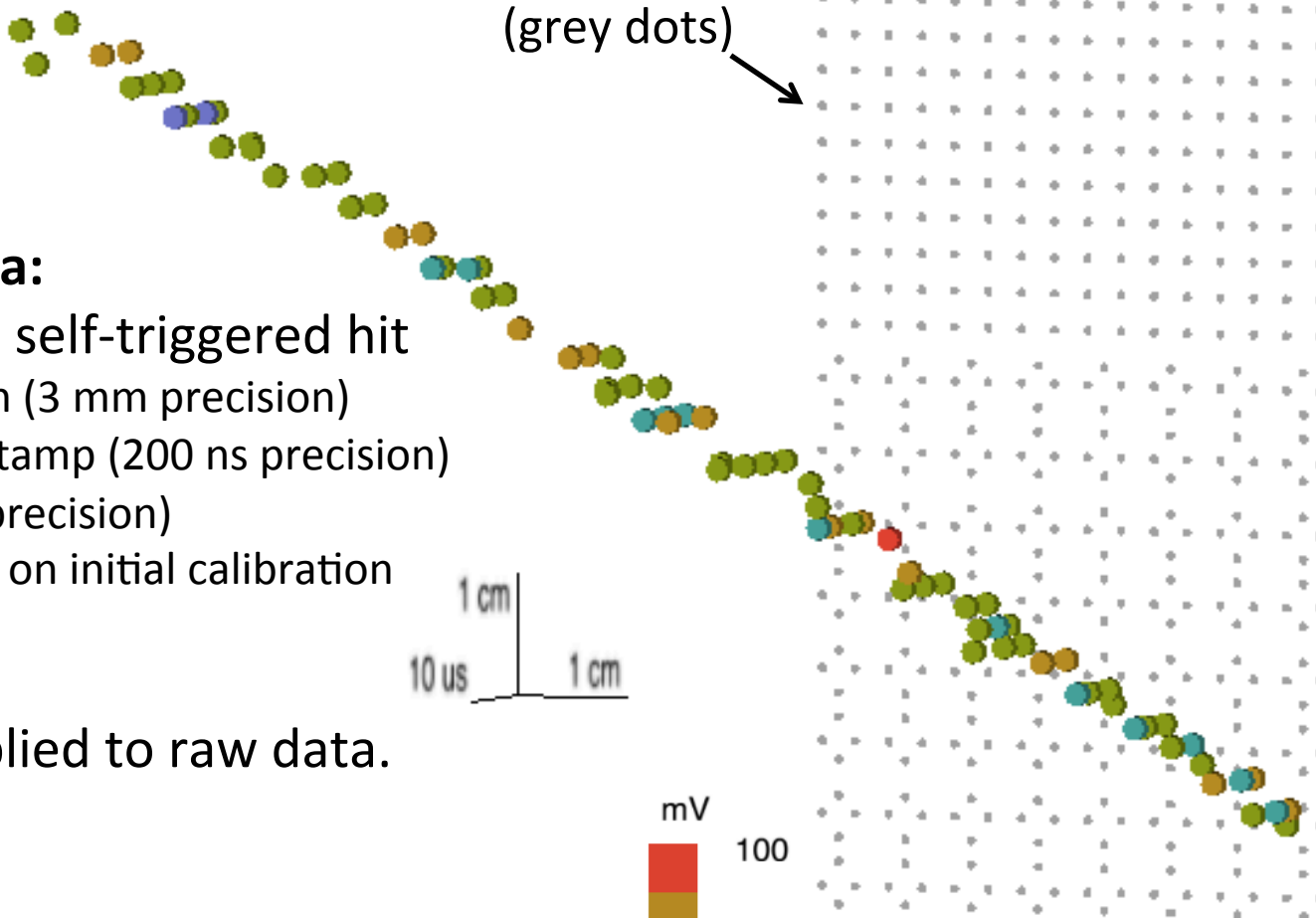
ArgonCube
Pixel

Demonstrator
(60-cm-drift
TPC)

Raised HV to 31.5 kV (500 V/cm)

→ Immediately observed cosmic ray tracks

512 pixels
(grey dots)



3D image from actual raw data:

Each colored point shows one self-triggered hit

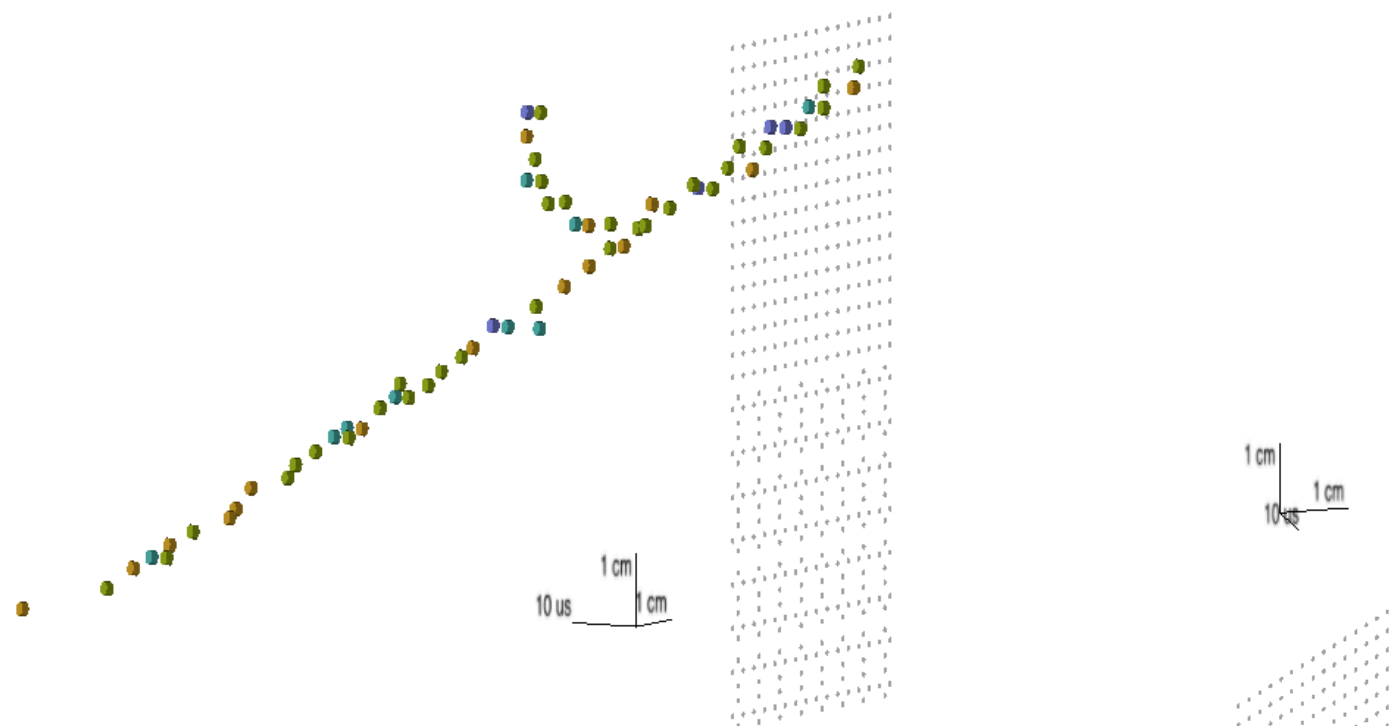
- Hit x, y position from pixel location (3 mm precision)
- Position along drift given by timestamp (200 ns precision)
- Color shows hit amplitude (2 mV precision)
- ADC value converted to mV based on initial calibration

No filtering, manipulation applied to raw data.

→ Noise is very low.

Operated 2 days at 500V/cm, then increased cathode voltage to 63 kV (1000 V/cm) for remaining 3 days.

Slightly more interesting topologies



Straight MIP (at 45° to sensor):

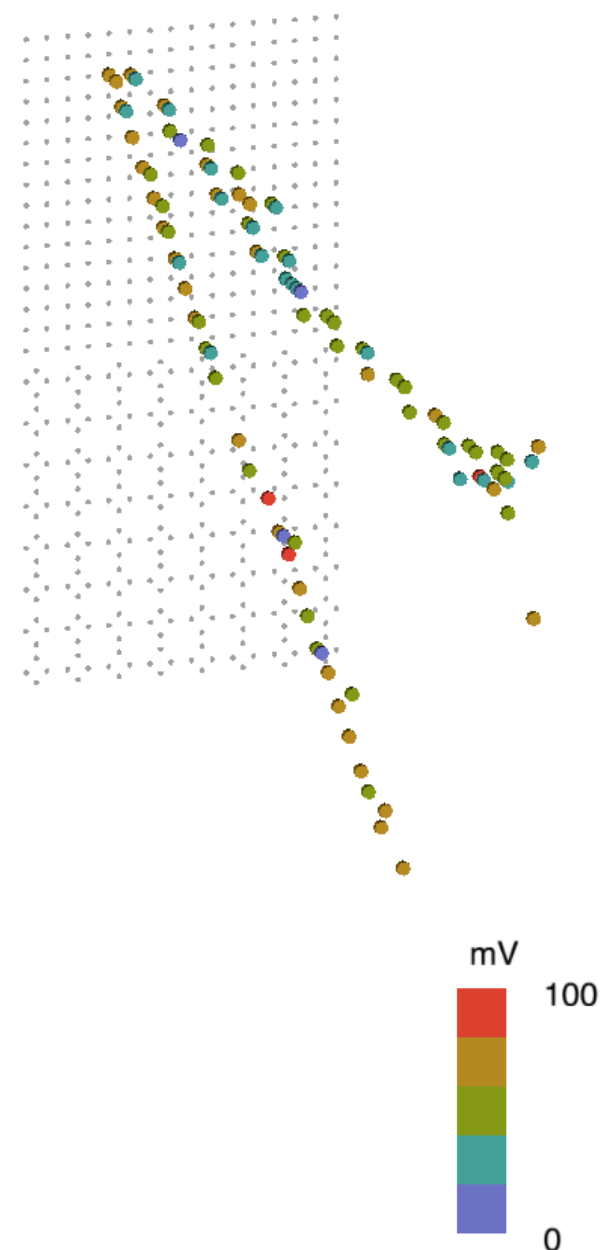
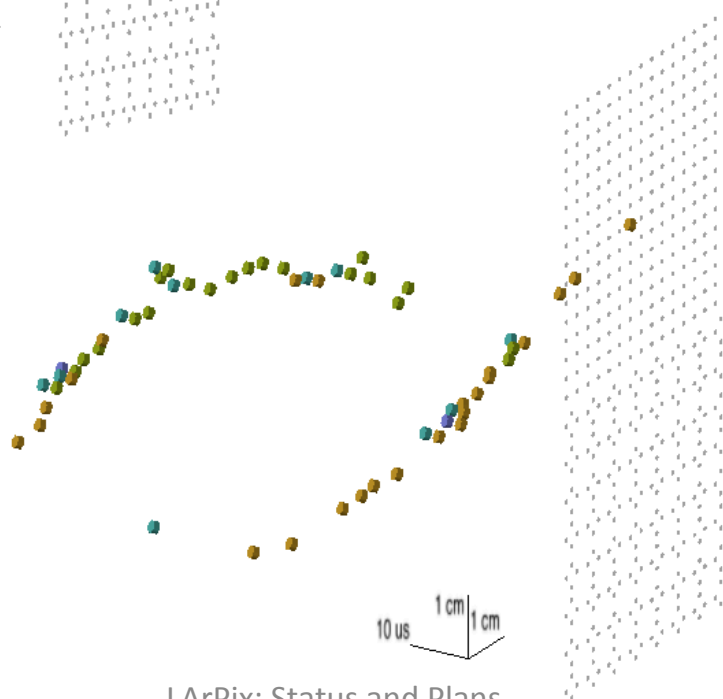
35 ± 5 ADC (over pedestal)

Noise:

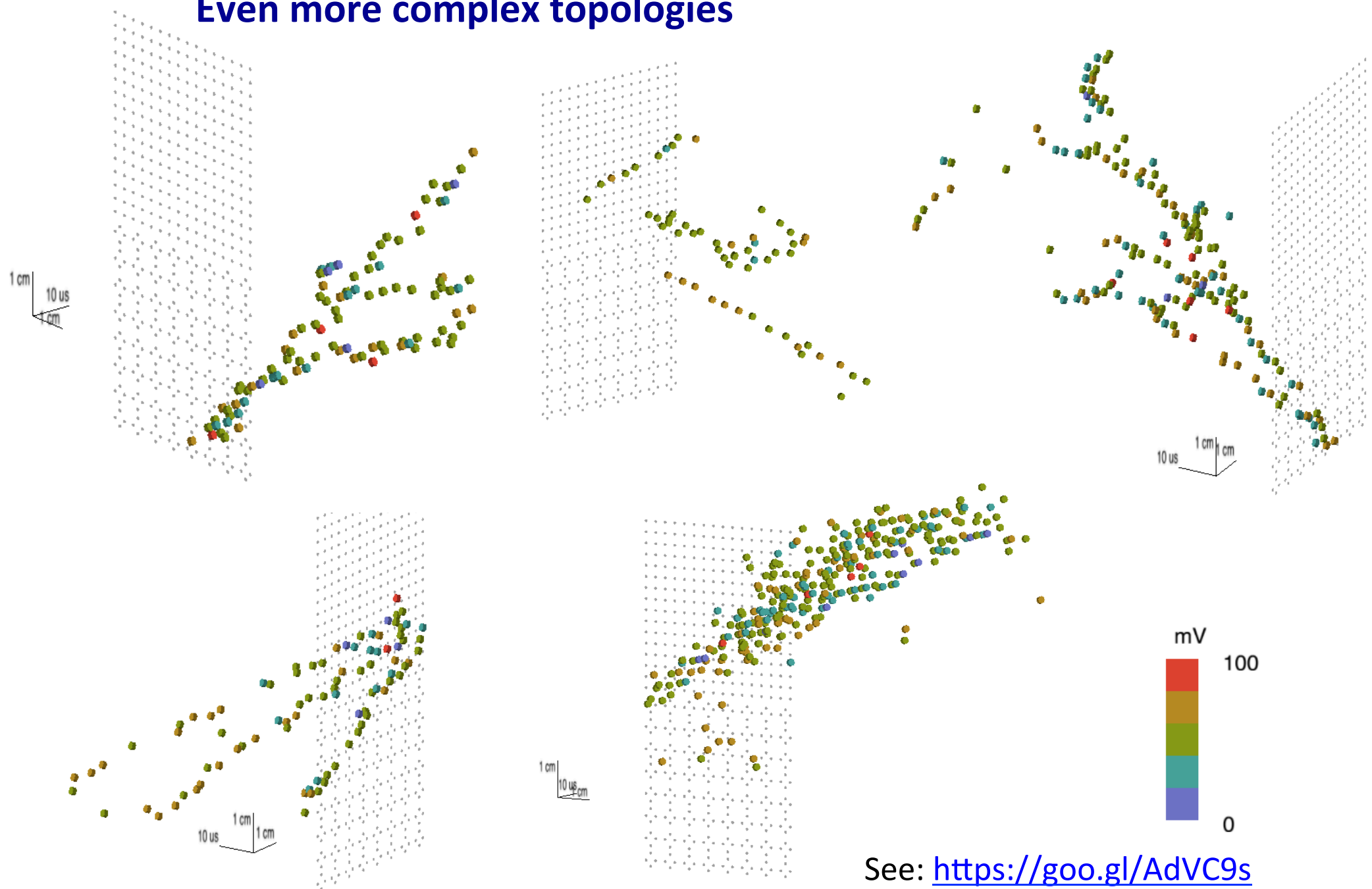
2 ± 0.5 ADC

S/N Ratio:

17 ± 3 ADC



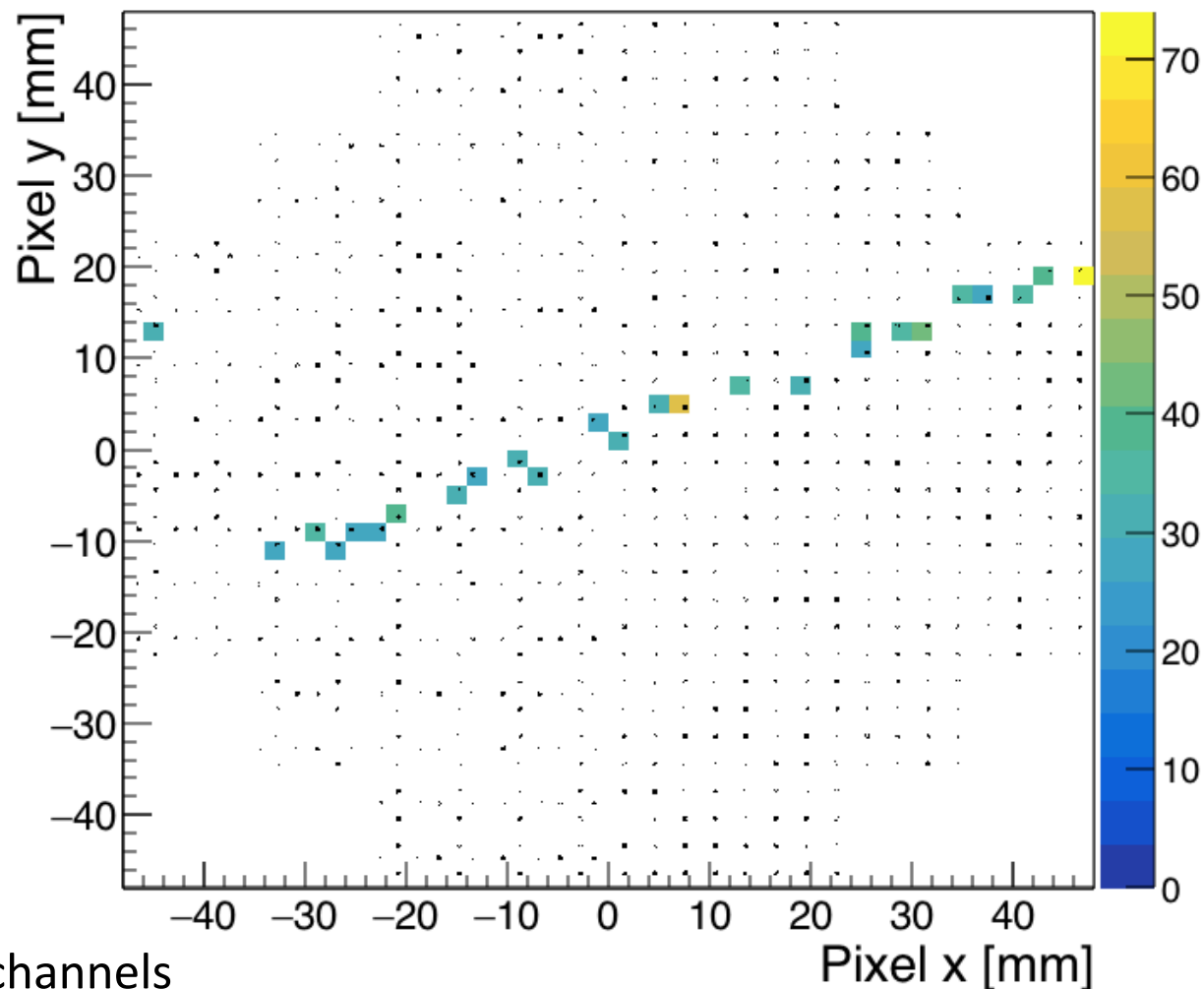
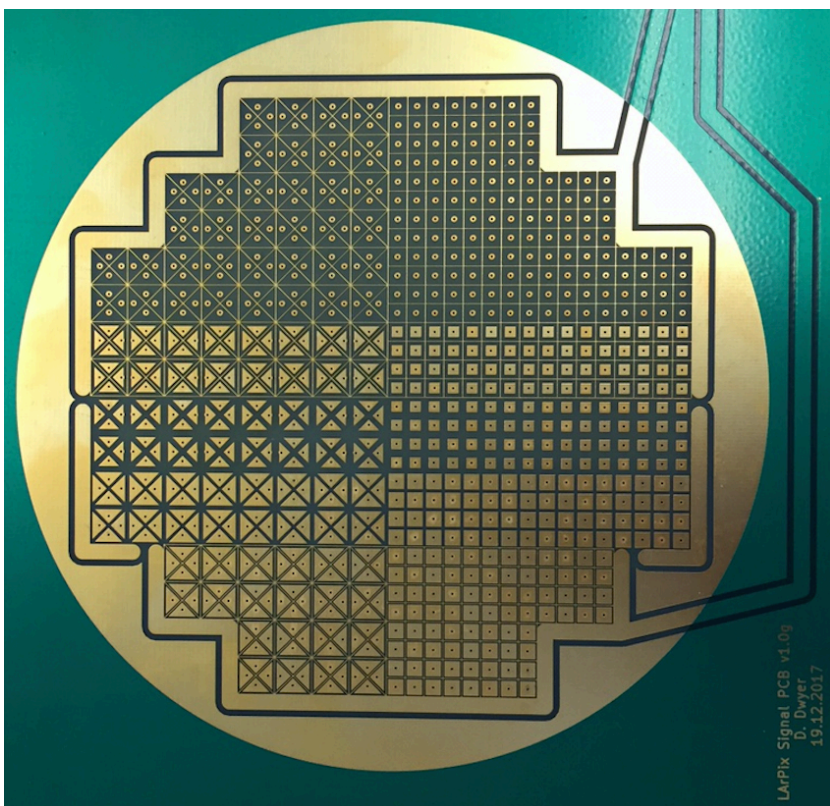
Even more complex topologies



See: <https://goo.gl/AdVC9s>

Completed full instrumentation of first-generation readout

datalog_2018_05_26_02_48_22_UT : Block 30821 (Sat, 26 May 2018 02:54:16 UTC +



May 21:

Began readout upgrade: 512 → 832 channels

May 25:

Completed testing in LArTPC @ LBNL

Initial conclusions: relative to test @ Bern

- System noise reduced by factor of ~4
- Poorer LAr purity → reduced data quality

Characterization of pixelated readout:

- 1) Establish calibration techniques
- 2) Comparison of performance of pixel types
→ Will determine the design for version 2 of Pixel Readout PCB
- 3) Assess performance of LArPix triggering and readout
→ Will motivate targets for LArPix version 2 ASIC design

See P. Madigan's talk

Near-term system revisions: targeting improved prototype system

- 1) v2 Readout PCB:
 - Improve isolation between pixel inputs and digital activity, and facilitate bypassing
 - Intermediate step toward modular readout tile
- 2) v2 Control Electronics (warm):
 - Work with LHEP to establish scalable ($>10^6$ pixel) control electronics
 - Stepping-stone to ArgonCube 2x2 control system
- 3) v2 Control Software:
 - Improve structure of high-level python configuration and control
 - Add flexible interface to low-level hardware communication with LArPix ASICs

*See S. Kohn's and
C. Tognina's talks*

Mid-term system revisions: targeting LArIAT, ArgonCube 2x2 Demonstrator

- 1) v2 LArPix ASIC (see next slide)
- 2) v3 Readout PCB (see slide after next)

Exploring LArPix-v2 for full physics performance:

Simultaneously obtain high resolution and large dynamic range for charge signal

(with LArPix-v1 you can only choose one or the other at a given time)

Make daisy chain I/O robust to chip failure.

Improve hit timestamp: catch rollover and remove jitter.

Reduce input pad voltage requirements.

Improve default configuration settings.

Improve handling of chip ID.

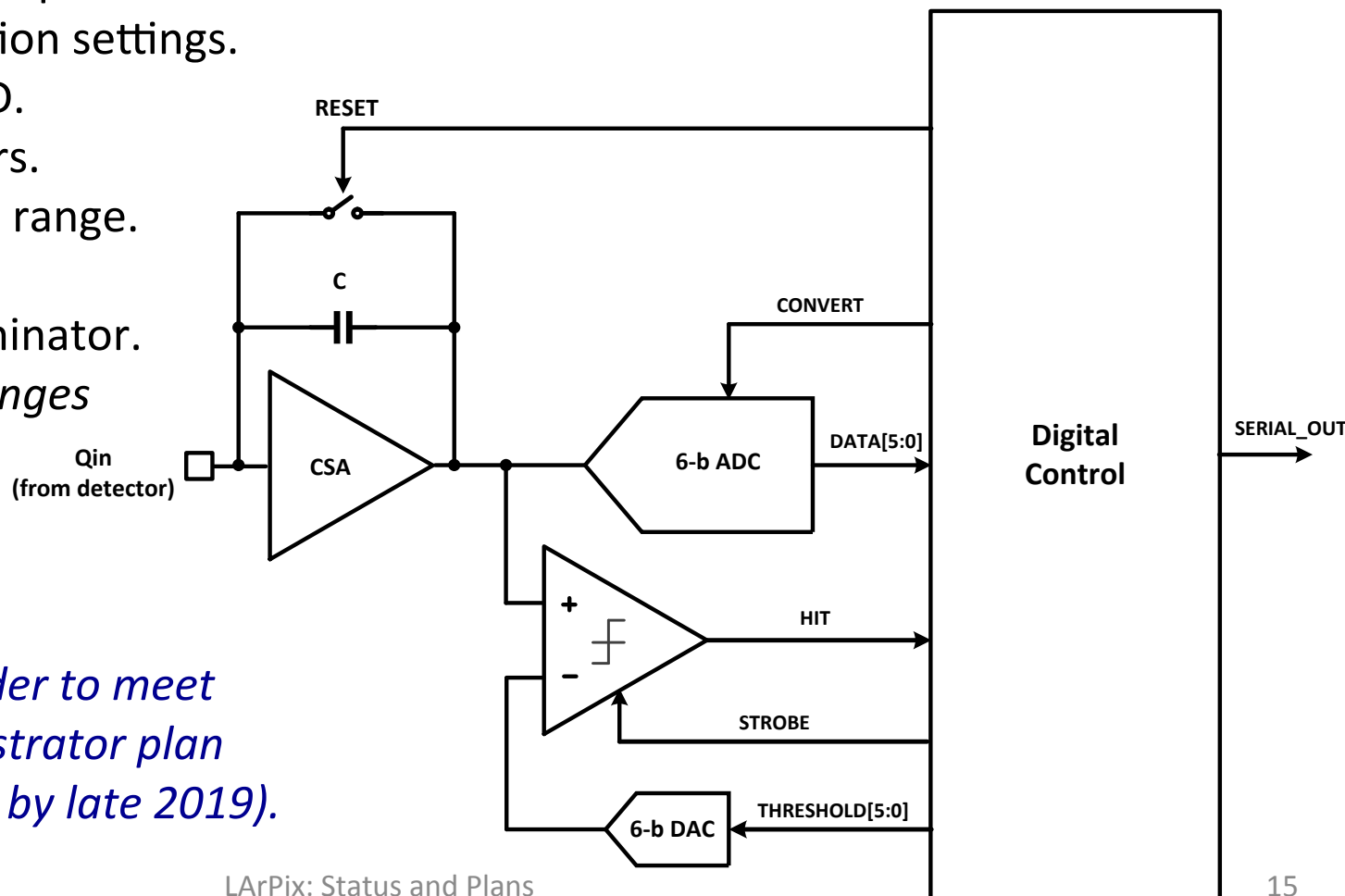
Add internal bias generators.

Increase channel threshold range.

Improve front-end pulser.

Tailor bandwidth of discriminator.

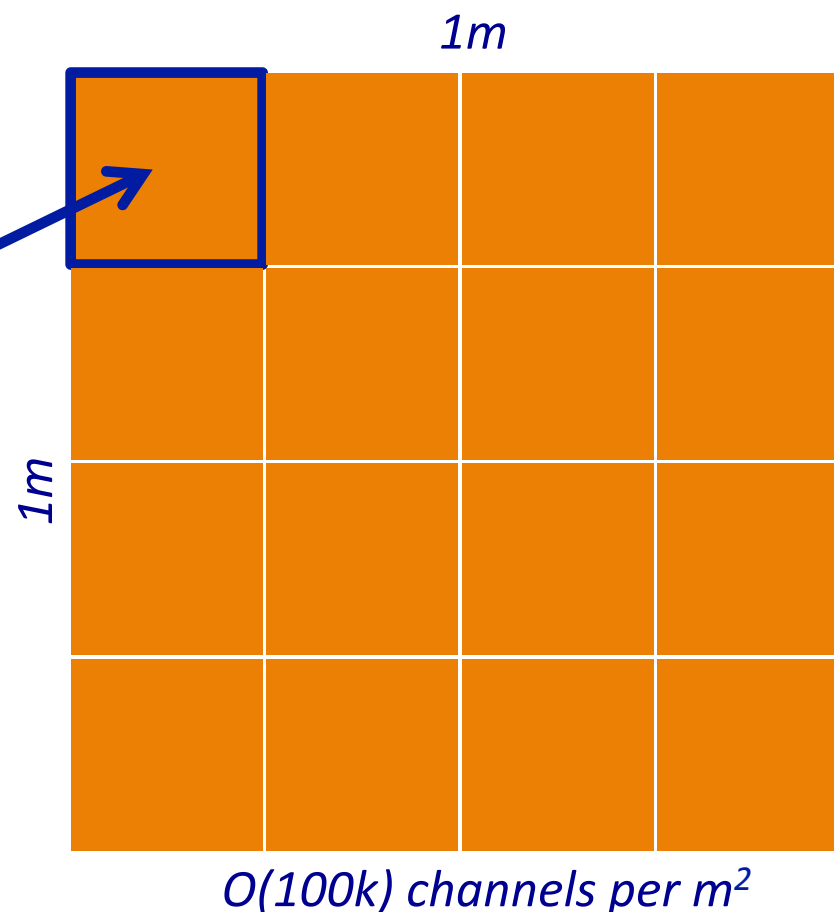
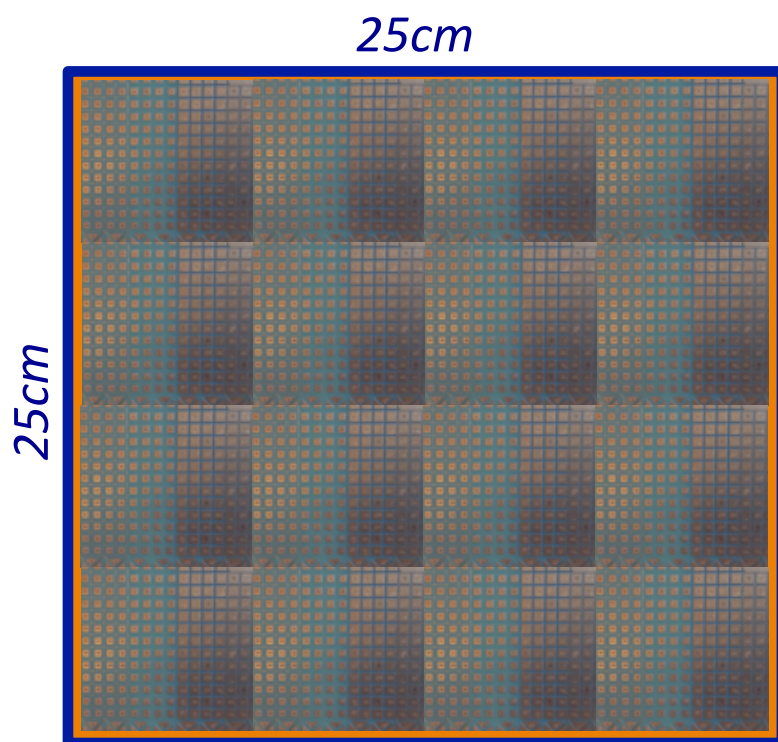
Plus a number of other changes



→ *Should start soon in order to meet ArgonCube 2x2 Demonstrator plan (~6 m² of readout ready by late 2019).*

Design modular pixel tile for instrumenting large area sensors

- Standard size (e.g. 25cm x 25cm)
- Easy to produce, assemble industrially
- One tile = one LArPix daisy chain

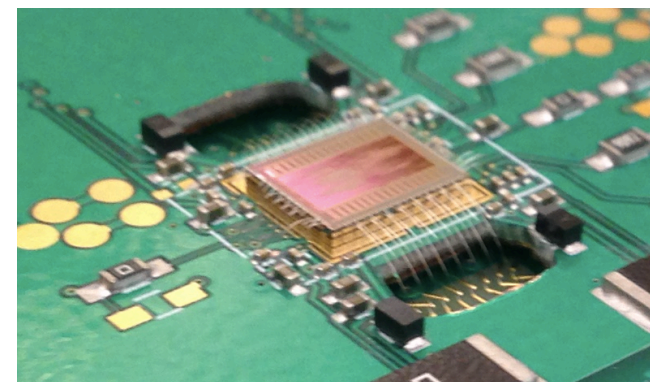


Demonstration targets:

- Spring 2019: LArIAT TPC: collect particle test beam data at FNAL
- Autumn 2019: ArgonCube 2x2 Demonstrator, 6- m^2 -scale, a stepping-stone to the DUNE Near Detector.

LArPix Characterization:

- 1) Is the current data sufficient to answer major questions:
 - Optimal pixel type for v2 readout?
 - Define targets for v2 ASIC design?
- 2) Do we aim for another near-term run @ Bern?
- 3) Schedule of joint publication on pixel readout performance?

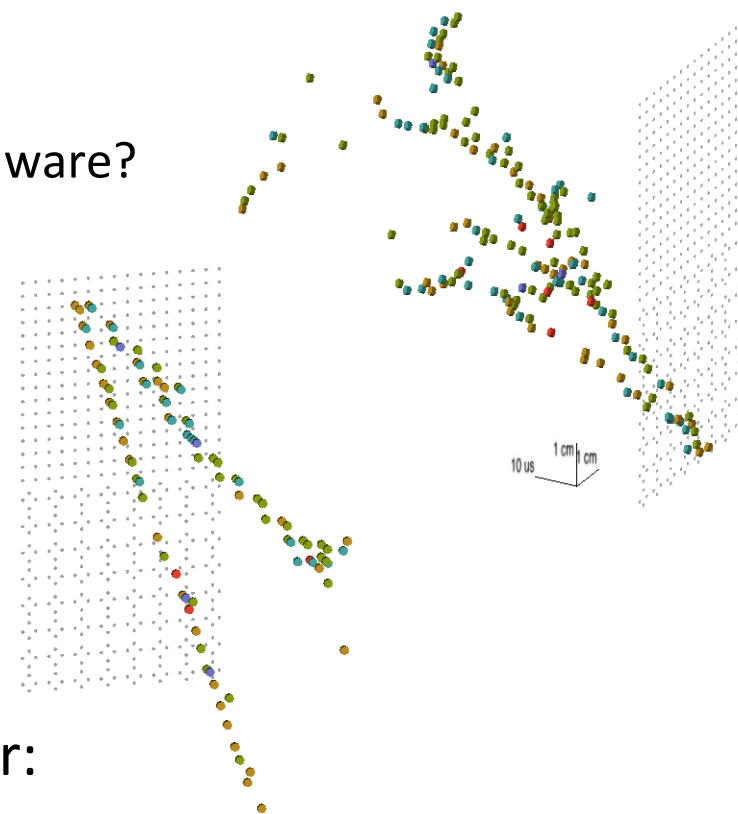


Scalable Control Hardware:

- 1) Plan and schedule for joint effort on scalable control hardware?

Readout for ArgonCube 2x2 Demonstrator:

- 1) Clear definition of scope and interfaces?
- 2) Detailed production schedule, integrated with 2x2 plan?
- 3) Complete end-to-end cost estimate?



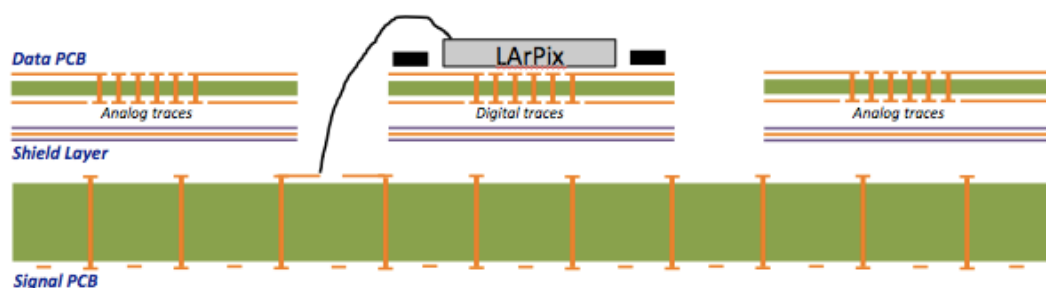
Much work needs to be done over the coming year:
→ *Glad to work with any other interested partners*



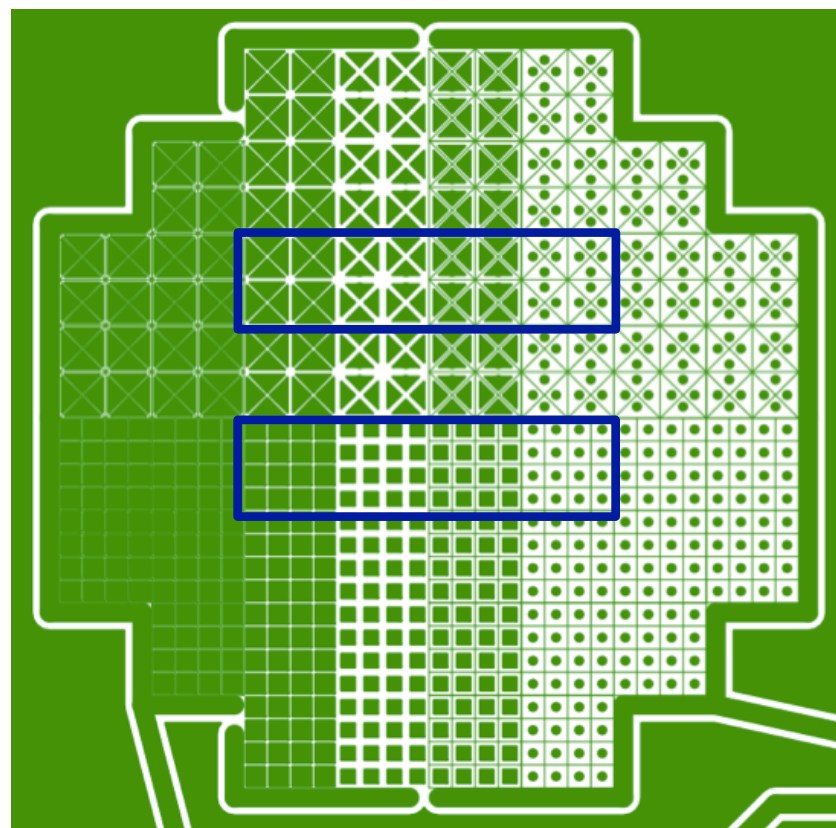
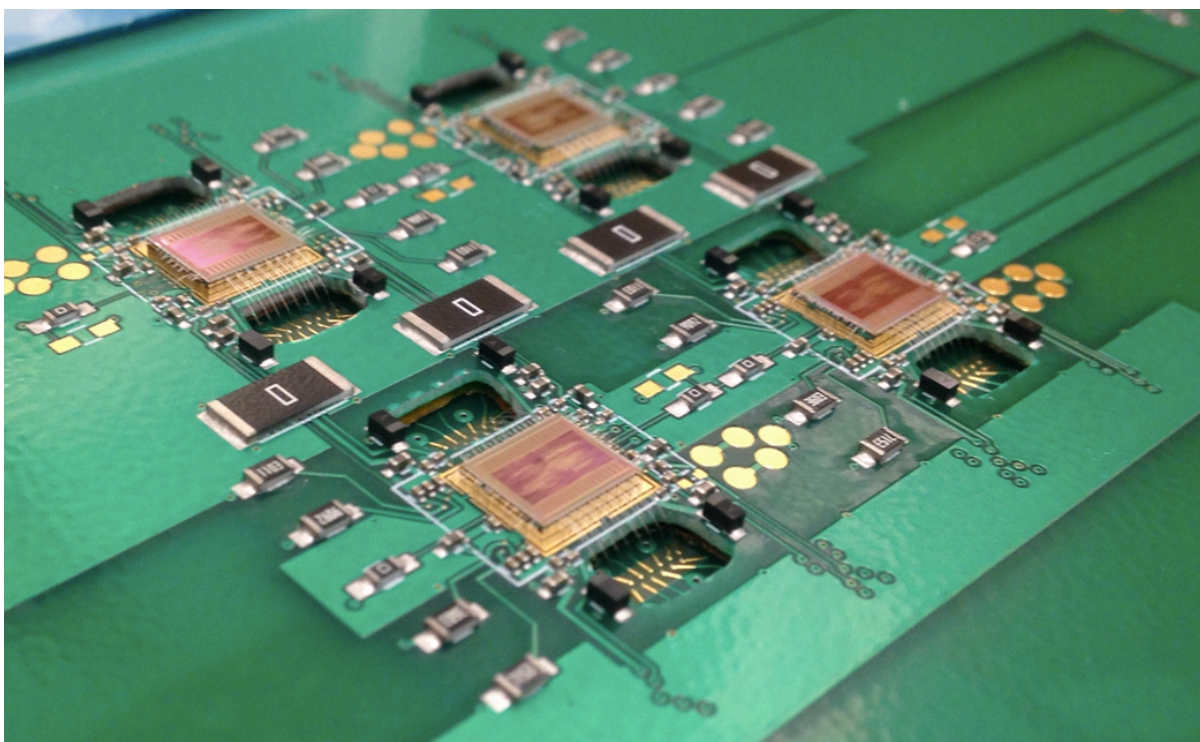
Backup

LArPix data board attached to sensor board

Careful consideration of system grounding and routing for low-noise operation
 First test: 128-chip data board used to partially instrument pixel readout plane

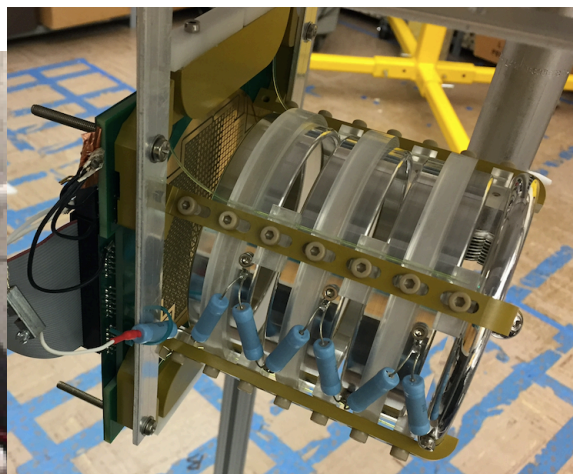
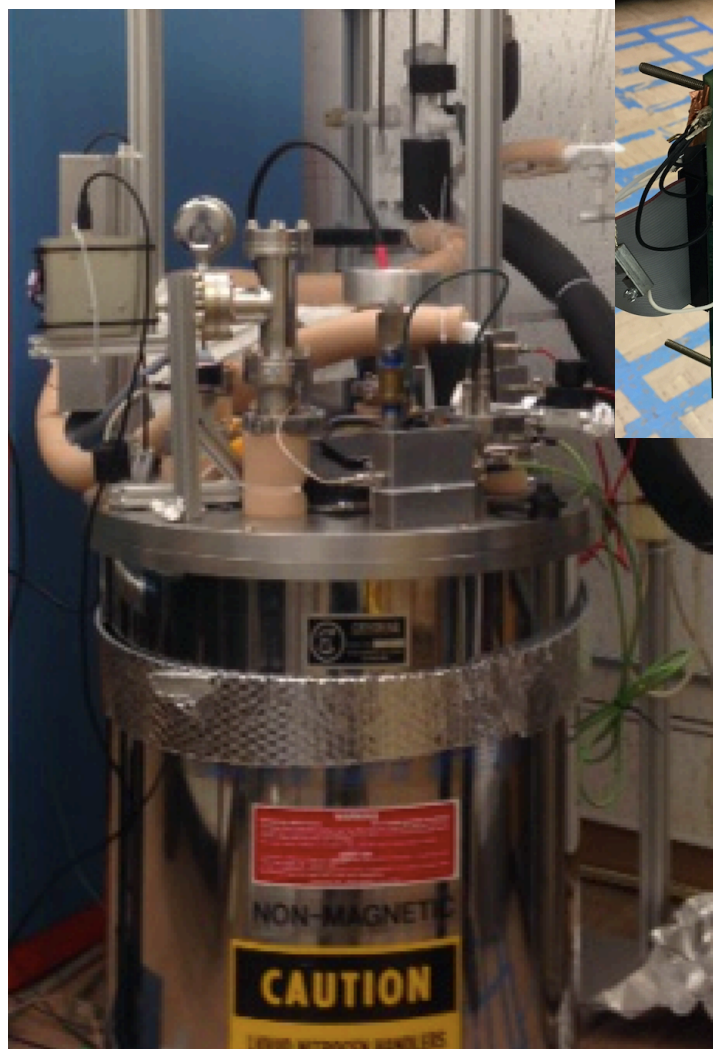


Instrumented regions

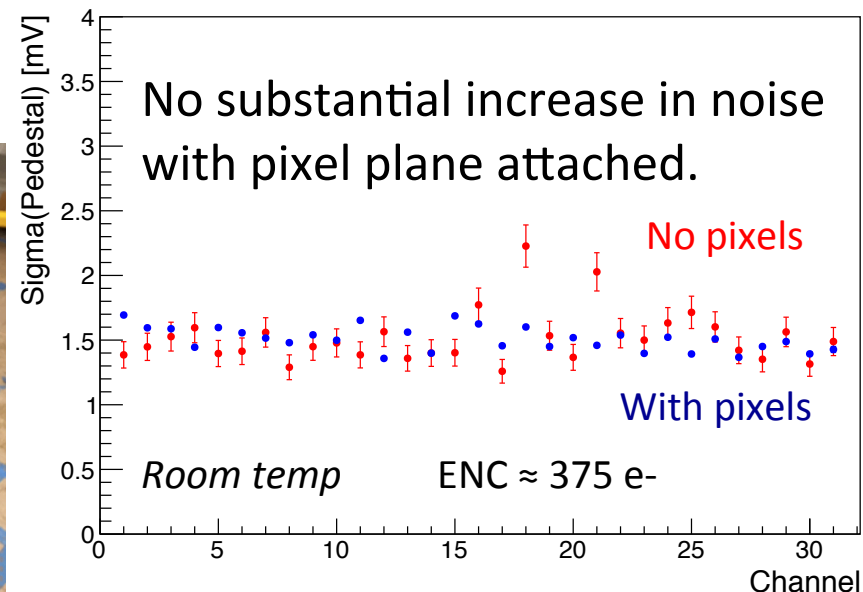


Initial LArTPC operation:

Borrowed LUX/LZ high-purity argon system
Using 10-cm-drift TPC from Bern



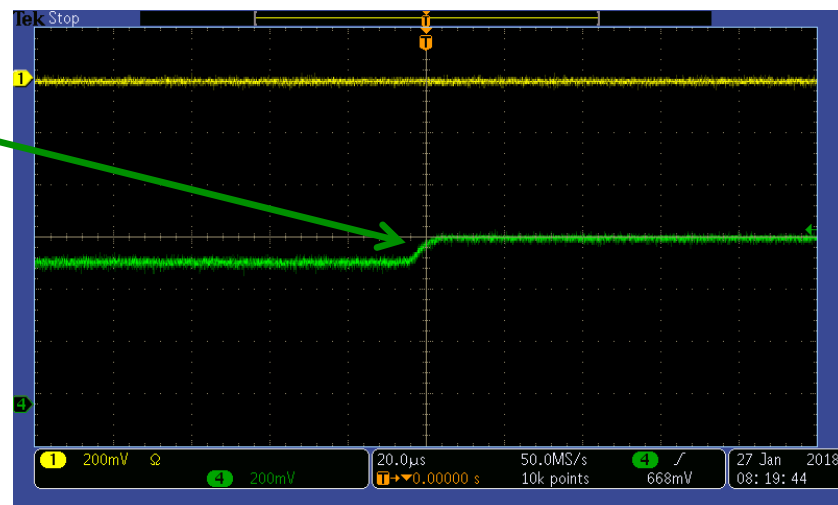
Readout assembly successful:



First cool-down: Jan. 26, 2018

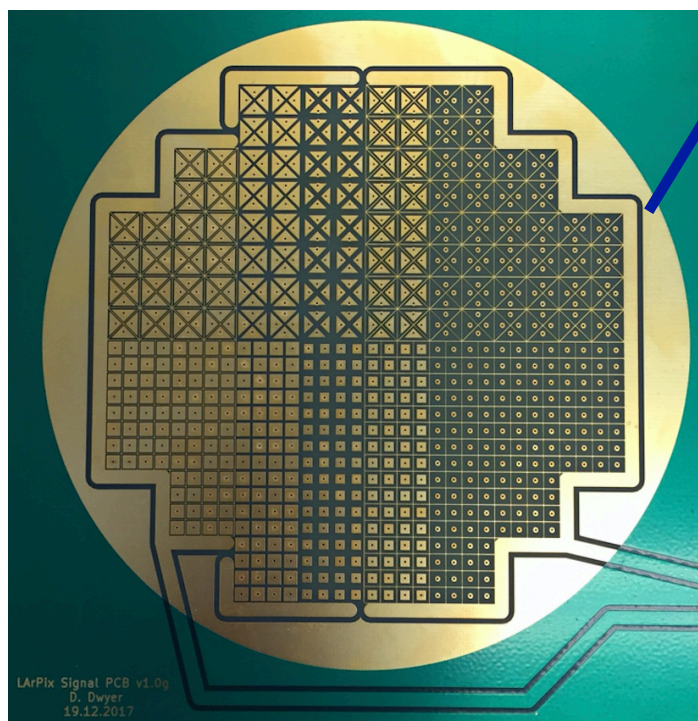
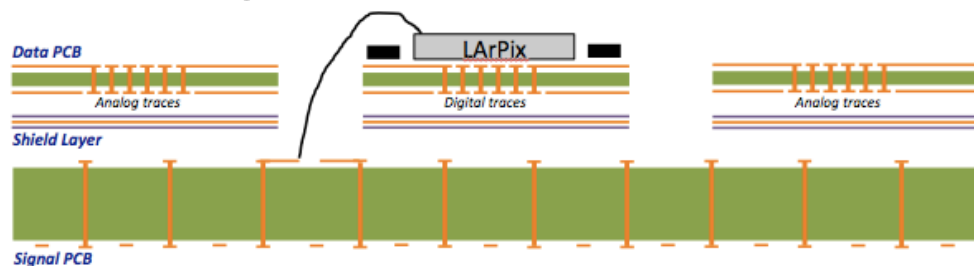
Observed pulses consistent with expectations

Example pulse consistent with ~25k e⁻ signal (using integrated analog monitor)

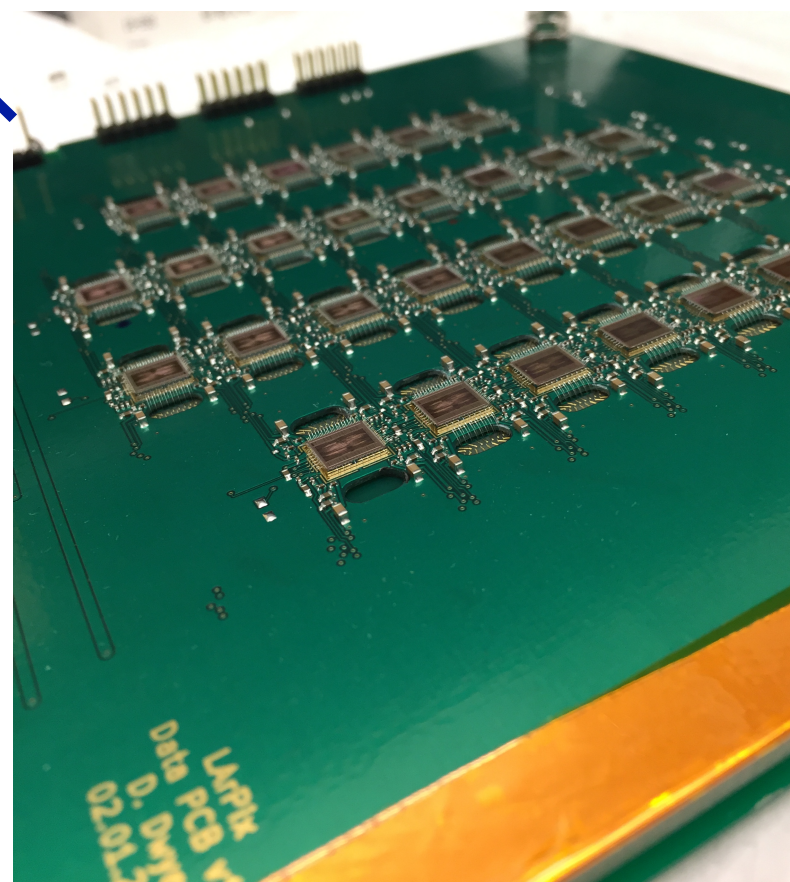


New Readout System:

- Designed new digital data board for scalable pixel readout (dense packing)
- Coupled to 10-cm diameter prototype pixel PCB board
 - Designed to fit both 10-cm-drift TPC (@LBNL) and 60-cm drift TPC (@Bern).



- 832 pixels
- 28 Chips



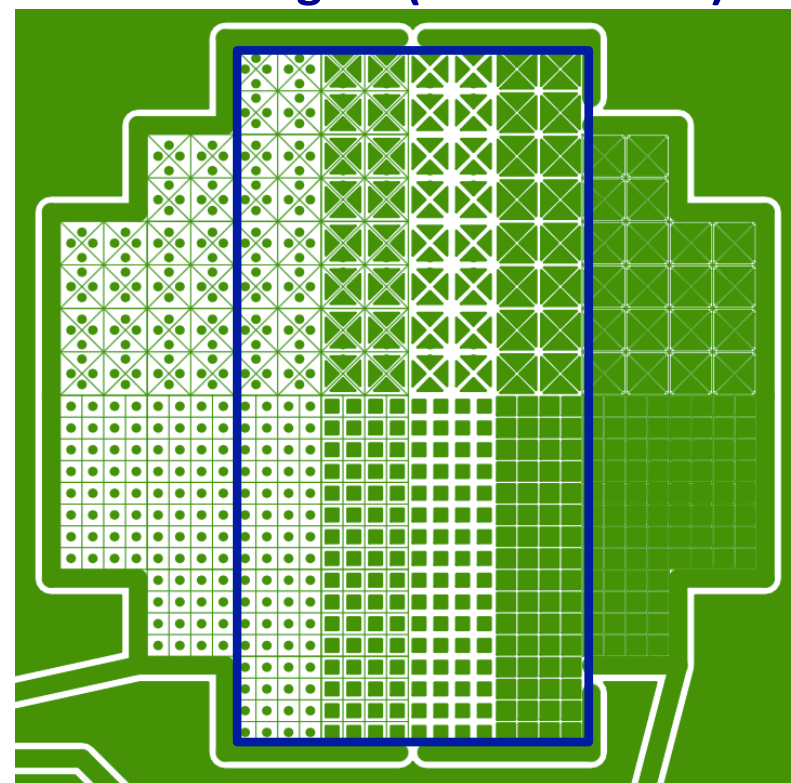
Summary of recent work

- Apr. 5: Wire bonder finished loading 28-chip readout board
 → *Found one chip not functional (DOA); insufficient time to replace, bypassed column 1.*
- Apr. 5 (evening): Tested and tuned readout at room temperature.
- Apr. 6: Operated in LAr to confirm cryo-functionality
- Apr. 7: Actively heated cryo-system to room temp, extracted readout, packed for Bern
- Apr. 8-9: Hand-carried readout and control to Bern
- Apr. 10: Warm test and debugging
 → *Found one chip damaged in transit or testing, bypassed column 4.*
- Apr. 10 (evening): Installed in 60-cm-drift TPC
- Apr. 11: Cooled, filled TPC with liquid argon
- Apr. 12-Apr. 19: TPC operation

Thanks to Sam Kohn, Peter Madigan for long hours preparing system for operation.

Thanks to entire Bern group for effective, round-the-clock TPC operation.

Active region (512 channels)



Column: 1 2 3 4

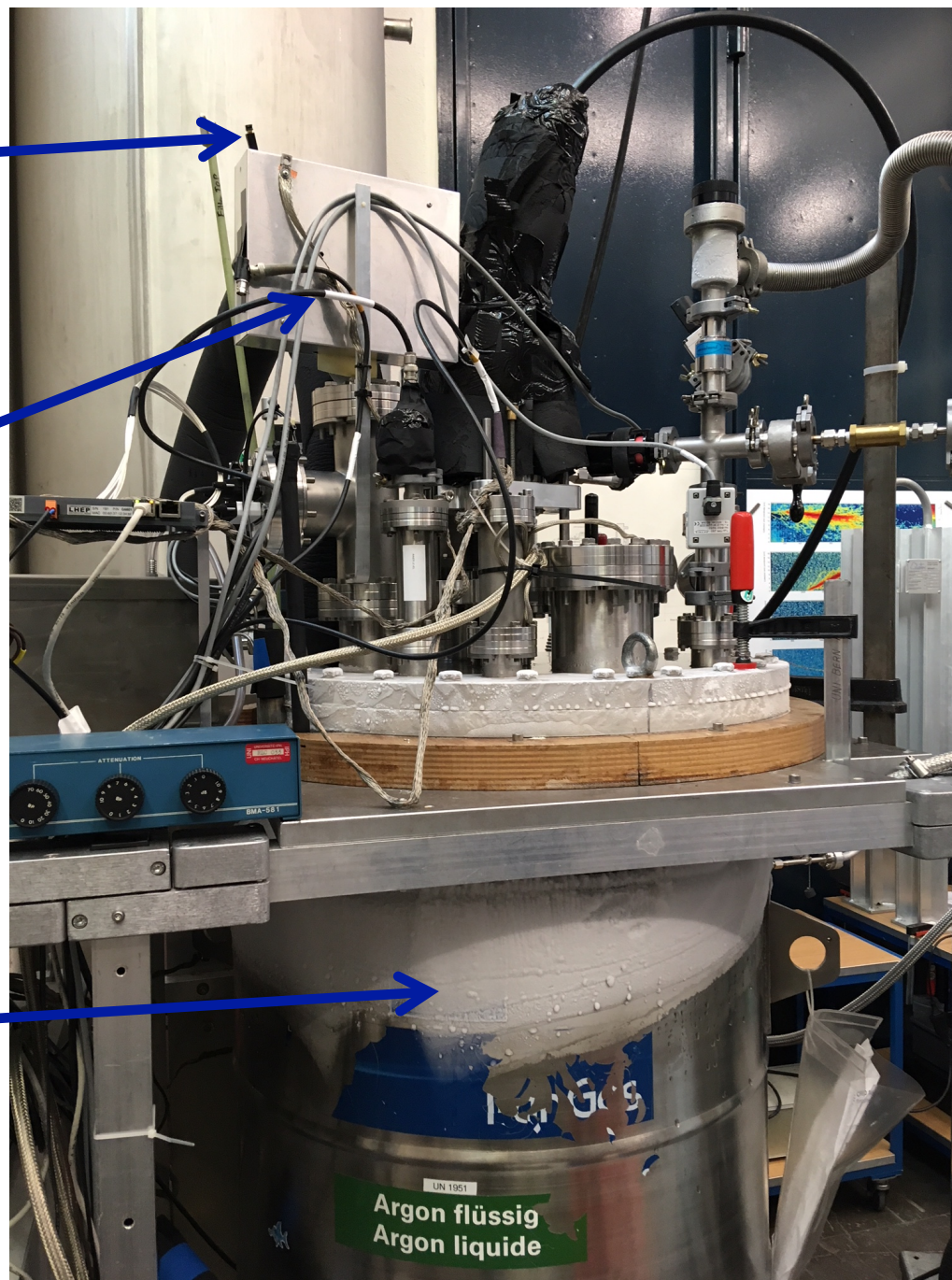
LArPix WiFi
Antenna

LArPix Control
System

TPC Installed
in LAr Cryostat

Description of LAr System:
(TPC, Cryostat, HV, etc.)

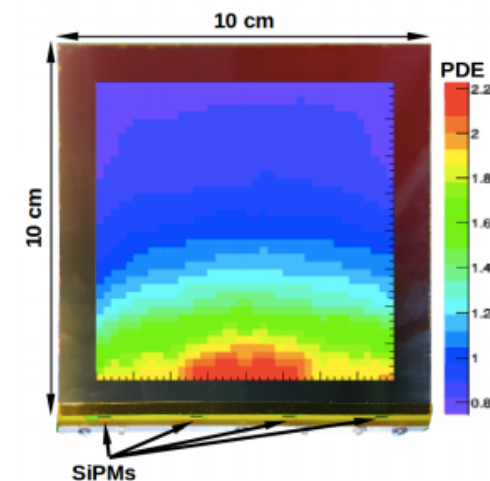
[arXiv:1801.08884](https://arxiv.org/abs/1801.08884)



ArCLight Photon Detection System:

- Independent DAQ
- Triggers on SiPM coincidences (8 SiPMs total)
- Issues trigger output signal, 1pps output signal

[ArCLight: arXiv:1711.11409](https://arxiv.org/abs/1711.11409)



Muon Telescope:

- Identifies muons oriented along 60-cm drift.
- 4 large scintillator paddles (two above, two below cryostat)
- Issues trigger output signal on 4-fold coincidence of all paddles

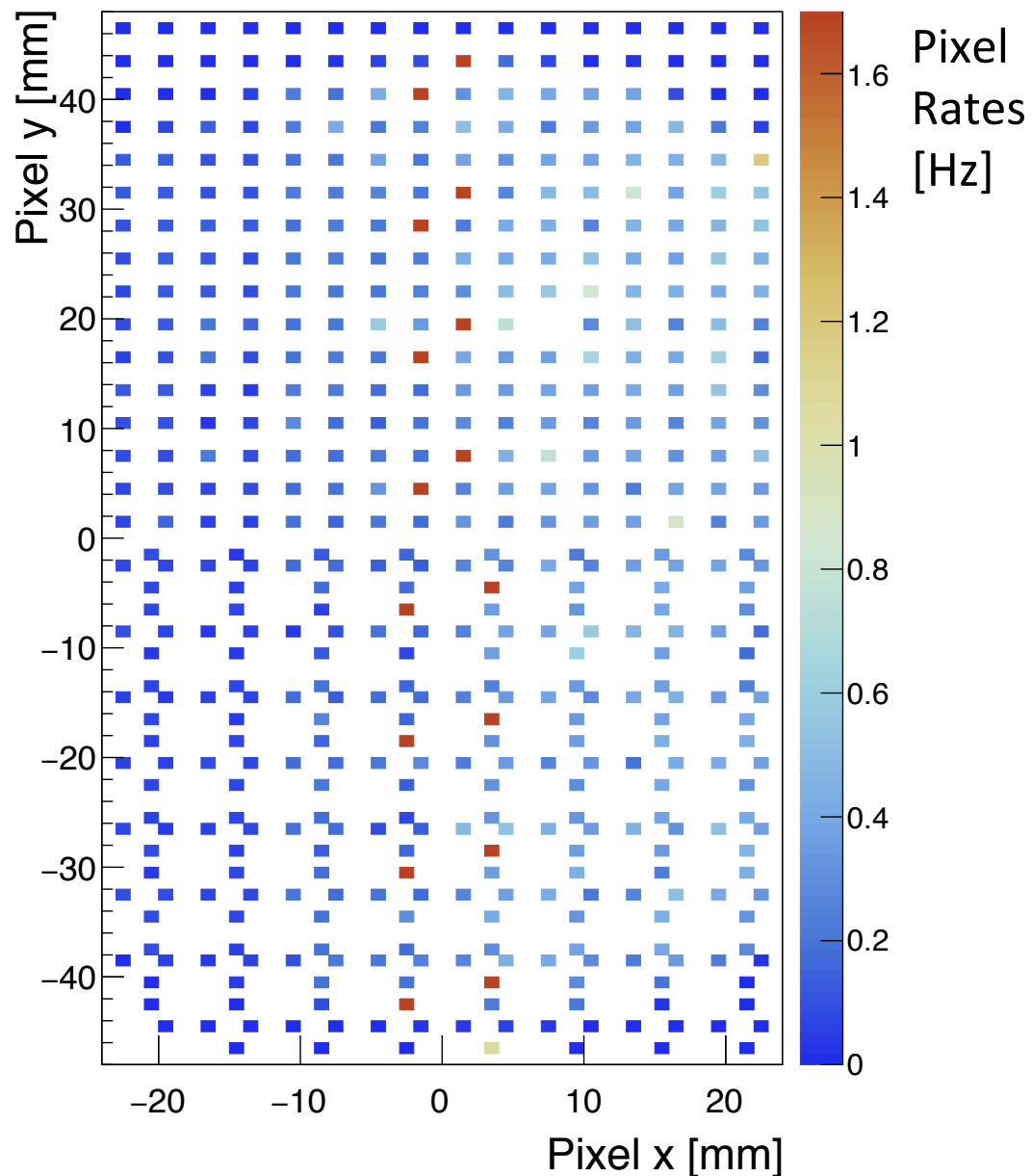
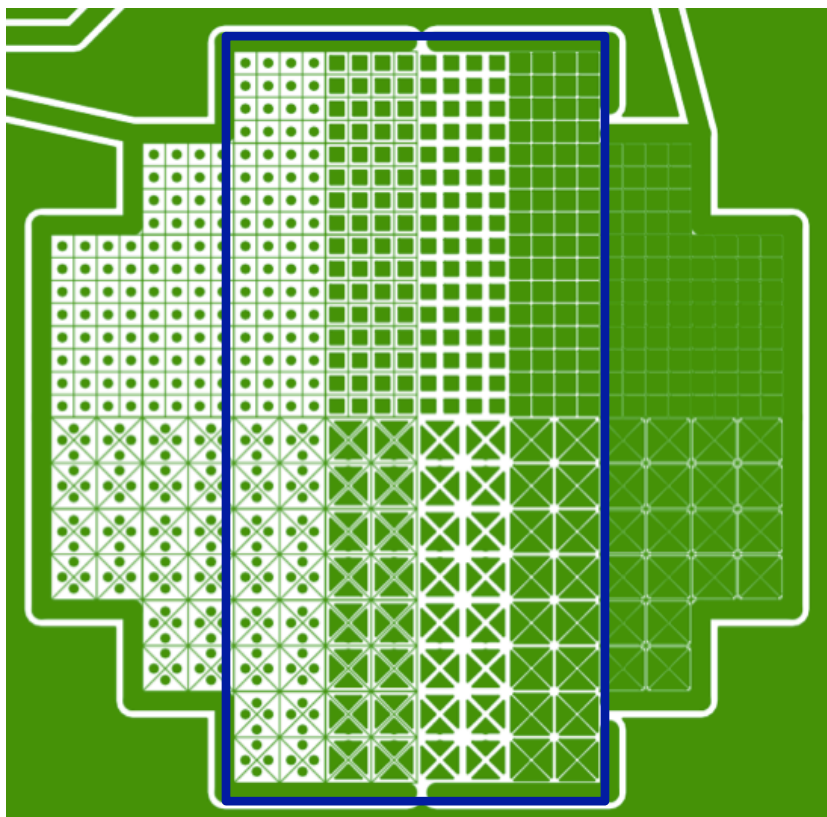
LArPix Charge Detection:

- Self-triggers on charge signal incident on any pixel
- Accepts ArCLight trigger, 1pps, Muon Telescope trigger output signals, and uses to imbed t_0 marker in LArPix data stream.

Pixel Trigger Rates

Observations:

- Red pixels: t_0 marker
- Top, bottom edges: lower rates due to TPC drift field non-uniformity
- Right side higher rate than left:
Combination of pad size and focusing grid (grid currently not biased)
- One pixel disabled due to high rate



System ran stably, continuously for entire week of LArTPC operation.